



One of the World's Largest
Manufacturers
of Discrete Semiconductors and Passive Components

Production Part Approval Process

The following PPAP documentation is assembled according to the AIAG, 4th Edition PPAP Manual and applicable customer requirements

IHLP5050FDERxxxM5A

Generic PPAP

Generic PPAP

5/23/2017

Production Part Approval Process

**The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements**

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Vishay / Dale Electronics

1505 East Hwy 50 Yankton, SD 57078, USA Phone (605) 665-9301 Fax (605) 668-4247

ONE OF THE WORLD'S LARGEST MANUFACTURERS OF DISCRETE SEMICONDUCTORS AND PASSIVE COMPONENTS

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Production Part Approval Process

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Section 1. Design Records

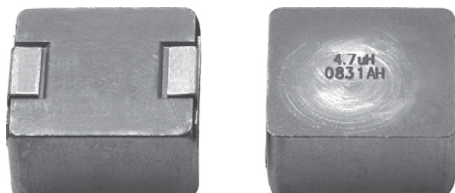
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ONE OF THE WORLD'S LARGEST MANUFACTURERS OF DISCRETE SEMICONDUCTORS AND PASSIVE COMPONENTS



IHLP® Automotive Inductors, High Temperature (155 °C) Series



DESIGN SUPPORT TOOLS click logo to get started



STANDARD ELECTRICAL SPECIFICATIONS

L_0 INDUCTANCE $\pm 20\%$ AT 100 kHz, 0.25 V, 0 A (μ H)	DCR TYP. 25 °C (m Ω)	DCR MAX. 25 °C (m Ω)	HEAT RATING CURRENT DC TYP. (A) ⁽¹⁾	SATURATION CURRENT DC TYP. (A) ⁽²⁾	SRF TYP. (MHz)
0.22	0.73	0.81	66	68	113
0.33	0.83	0.92	62	44	79.6
0.47	1.05	1.16	54	42	65.6
1.0	1.65	1.77	40	26	33.4
1.2	1.98	2.12	29	24.5	32.0
1.5	2.4	2.57	27.5	23.5	29.2
1.8	2.75	2.94	26	22.5	25.9
2.2	3.43	3.67	25.5	21.5	23.3
3.3	5.08	5.44	20.2	16.7	17.8
4.7	7.41	7.93	17.4	18.5	15.8
5.6	8.51	9.11	15.7	14.2	12.3
6.8	11.3	12.09	14.2	8.7	13.4
7.8	12.6	13.48	13.5	8.5	13.6
8.2	13.2	14.12	13.2	7.6	10.3
10	16.60	17.76	10.9	7.2	10.7
12	19.00	20.33	10.6	6.9	7.59
15	24.00	25.68	8.7	6.8	8.30
22	31.30	33.49	8.3	5.5	6.43

Notes

- All test data is referenced to 25 °C ambient
- Operating temperature range -55 °C to +155 °C
- The part temperature (ambient + temp. rise) should not exceed 155 °C under worst case operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application
- Rated operating voltage (across inductor) = 75 V
- ⁽¹⁾ DC current (A) that will cause an approximate ΔT of 40 °C
- ⁽²⁾ DC current (A) that will cause L_0 to drop approximately 20 %

DESCRIPTION

IHLP-5050FD-5A	4.7 μ H	$\pm 20\%$	ER	e3
MODEL	INDUCTANCE VALUE	INDUCTANCE TOLERANCE	PACKAGE CODE	JEDEC® LEAD (Pb)-FREE STANDARD

GLOBAL PART NUMBER

I	H	L	P	5	0	5	0	F	D	E	R	4	R	7	M	5	A
MODEL				SIZE						PACKAGE CODE		INDUCTANCE VALUE			TOL.	SERIES	

PATENT(S): www.vishay.com/patents

This Vishay product is protected by one or more United States and international patents.

FEATURES

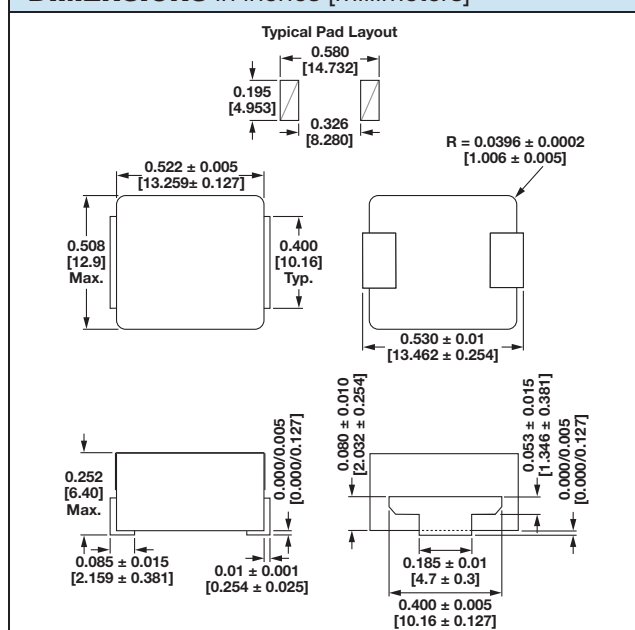
- High temperature, up to 155 °C
- Shielded construction
- Excellent DC/DC energy storage up to 1 MHz to 2 MHz. Filter inductor applications up the SRF (see Standard Electrical Specifications table).
- Lowest DCR/ μ H, in this package size
- Handles high transient current spikes without saturation
- Ultra low buzz noise, due to composite construction
- AEC-Q200 qualified
- IHLP design. PATENT(S): www.vishay.com/patents
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

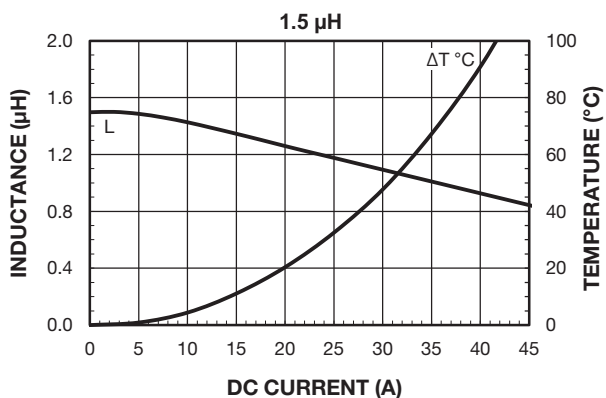
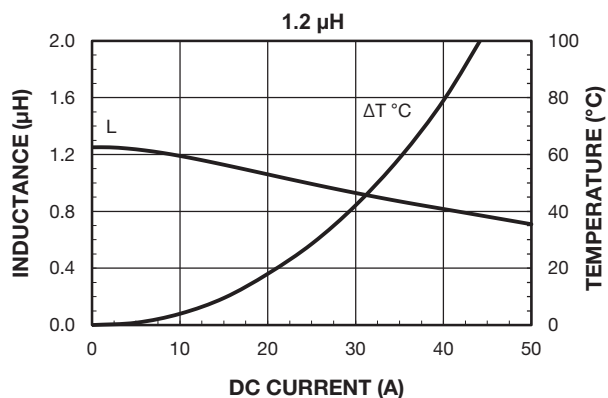
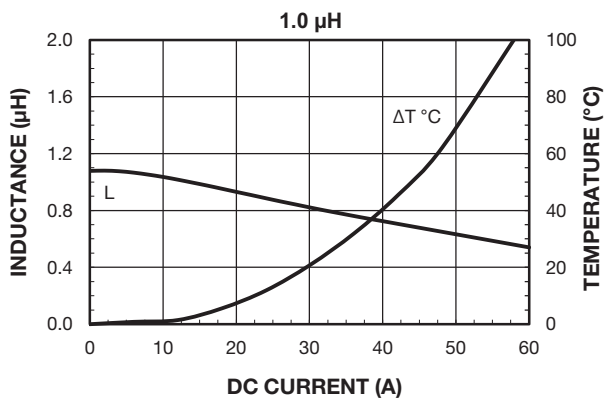
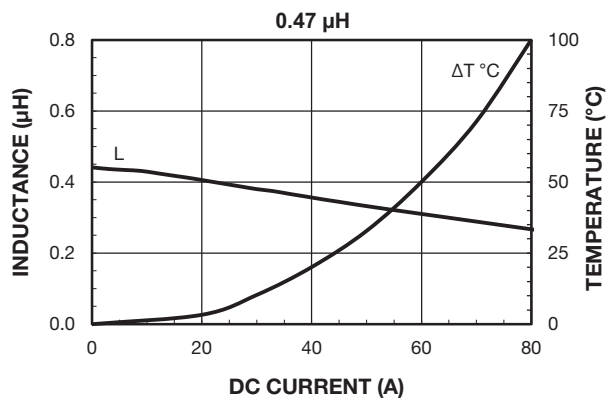
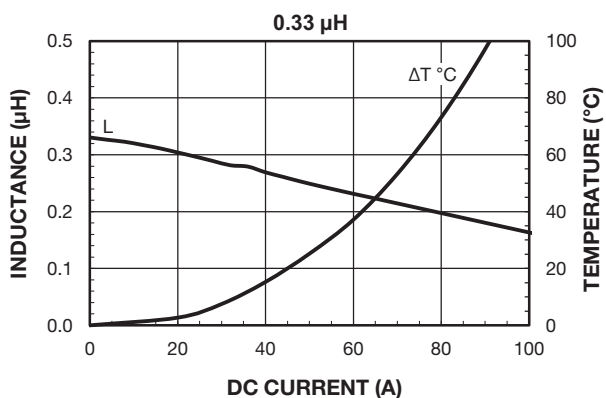
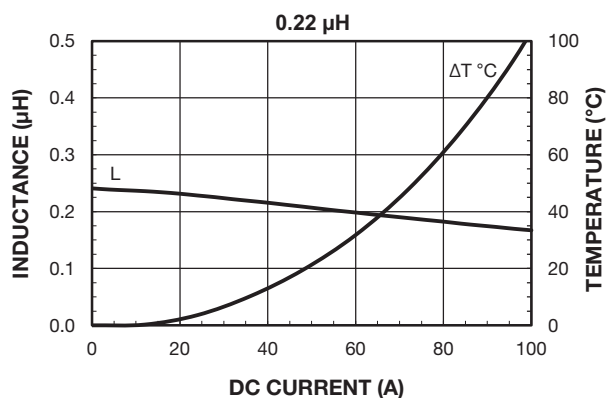
- Engine and transmission control units
- Diesel injection drivers
- DC/DC converters for entertainment / navigation systems
- Noise suppression for motors: windshield wipers / power seats / power mirrors / heating and ventilation blower / HID lighting
- LED drivers

DIMENSIONS in inches [millimeters]



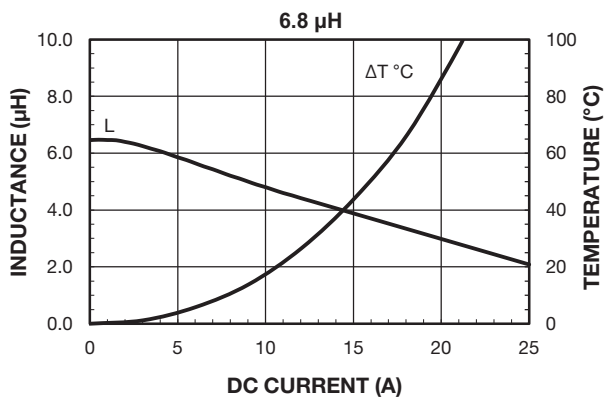
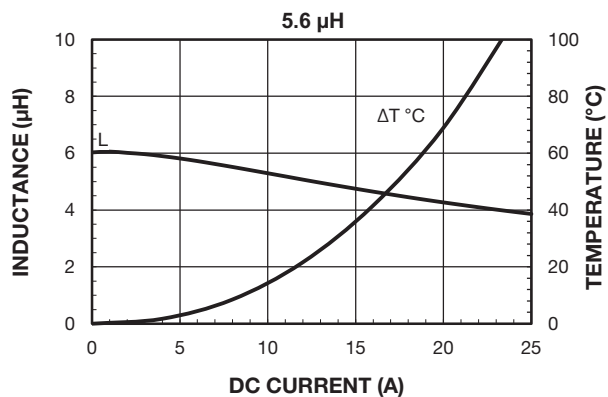
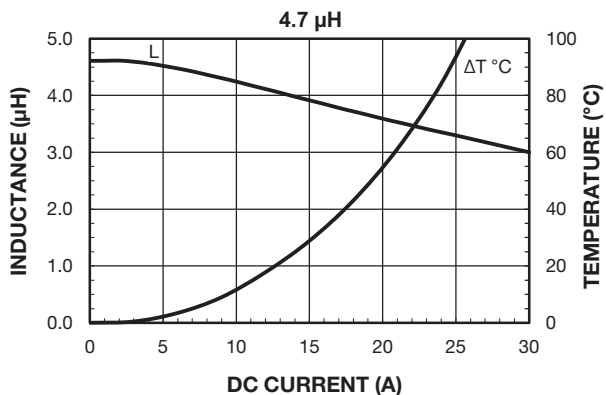
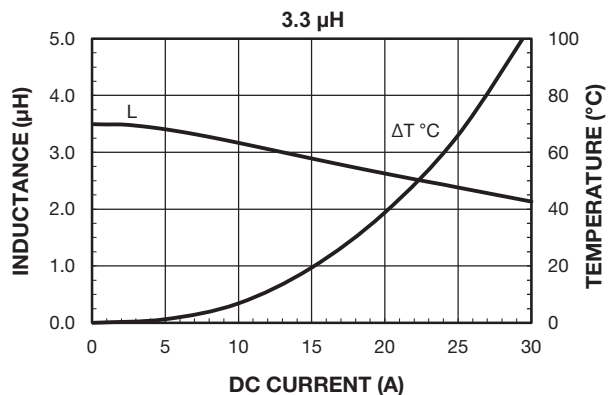
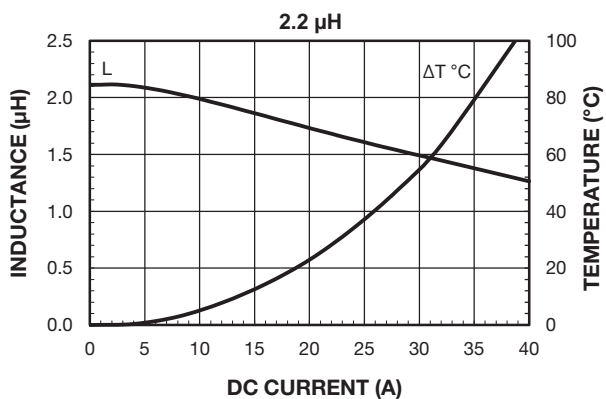
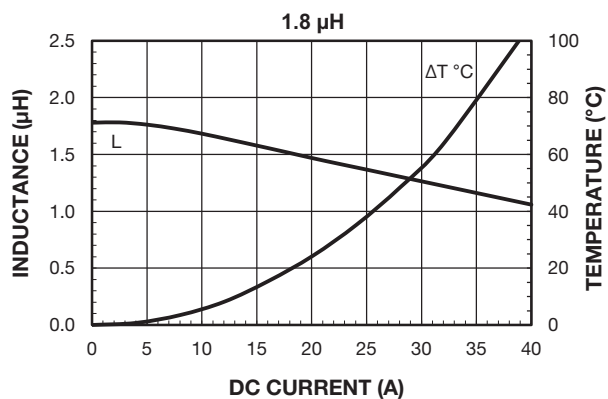


PERFORMANCE GRAPHS



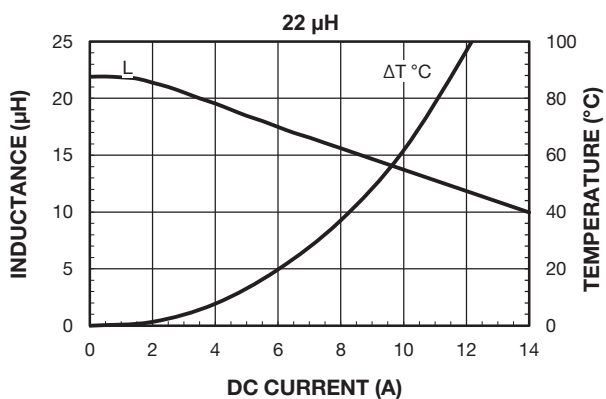
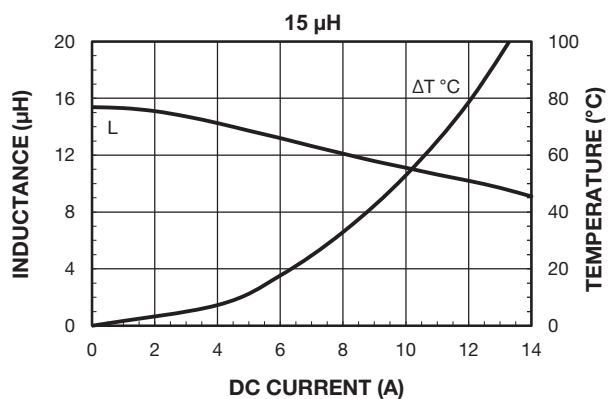
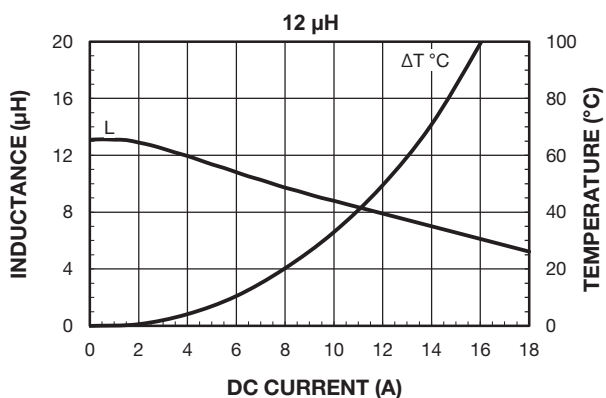
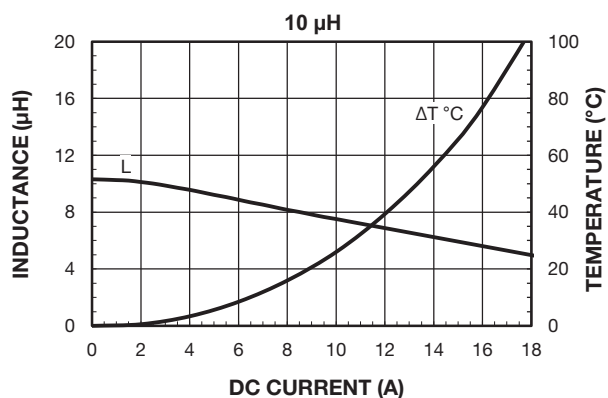
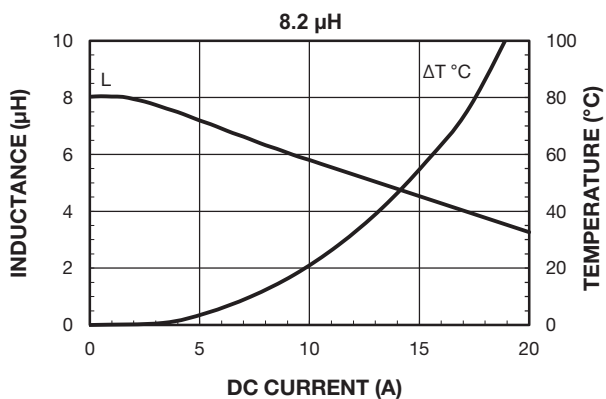
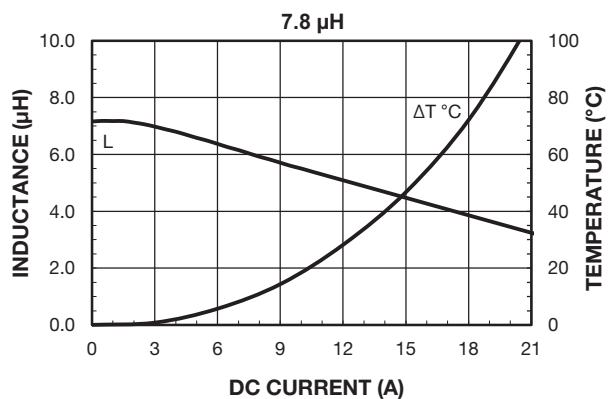


PERFORMANCE GRAPHS



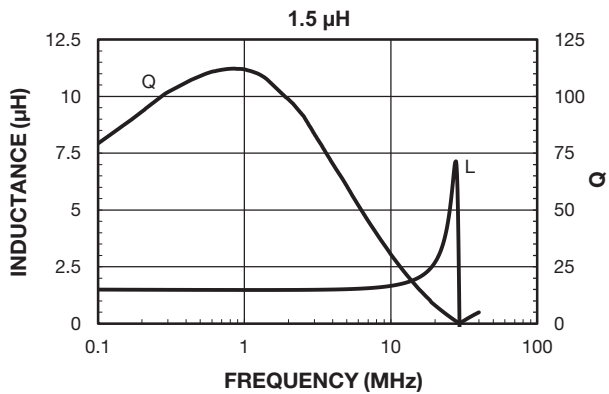
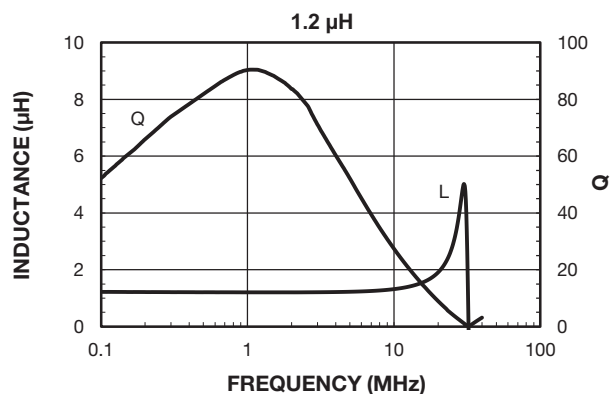
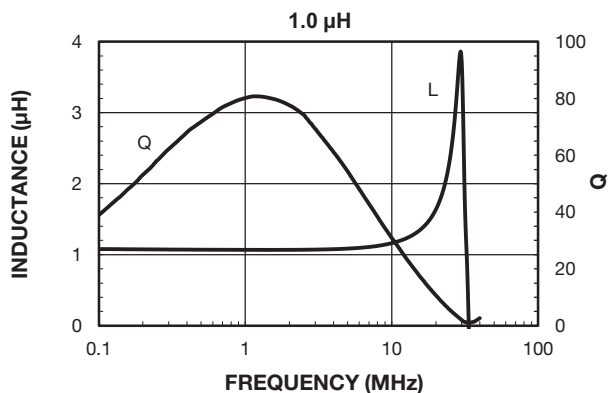
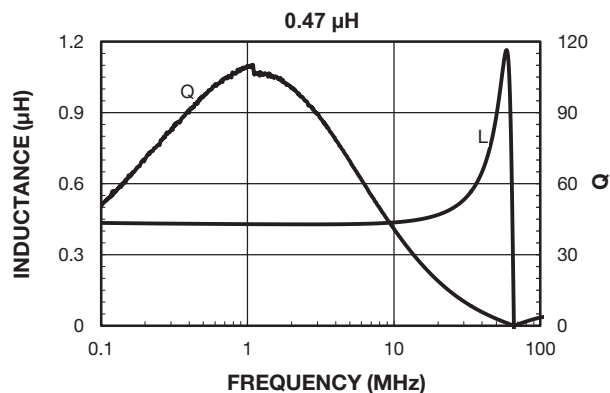
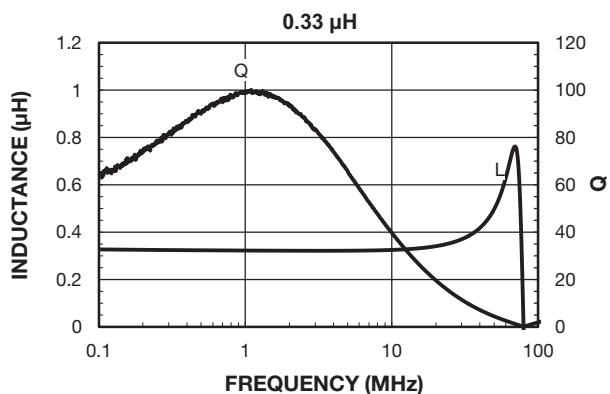
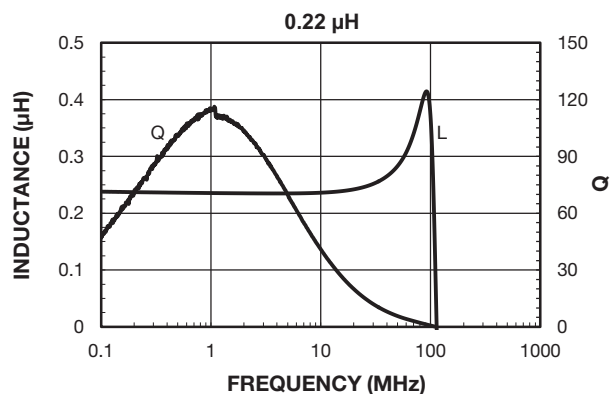


PERFORMANCE GRAPHS



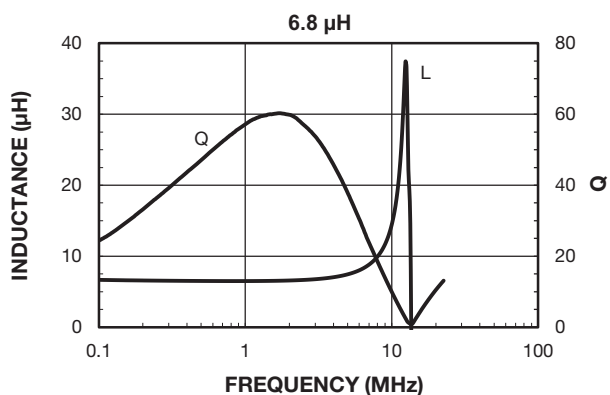
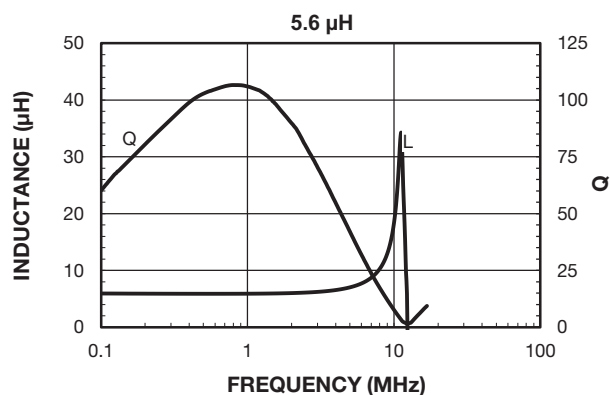
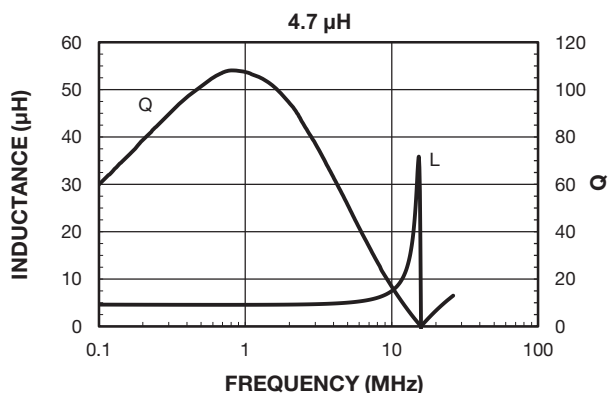
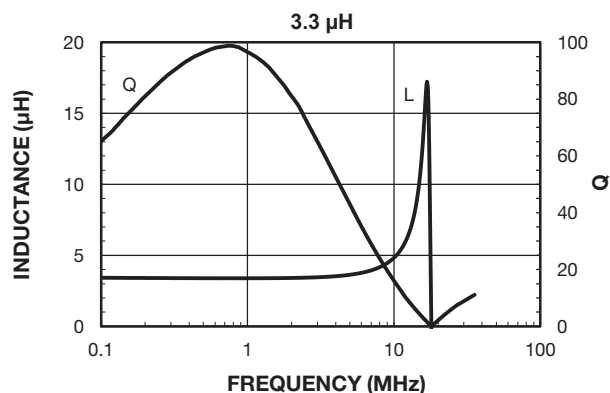
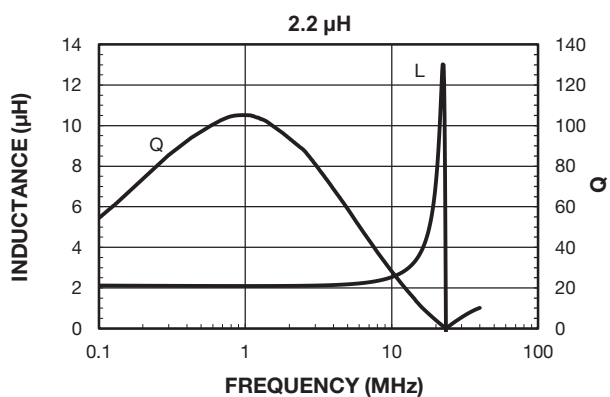
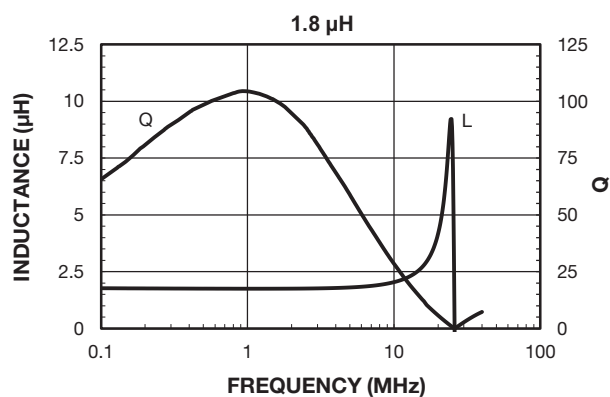


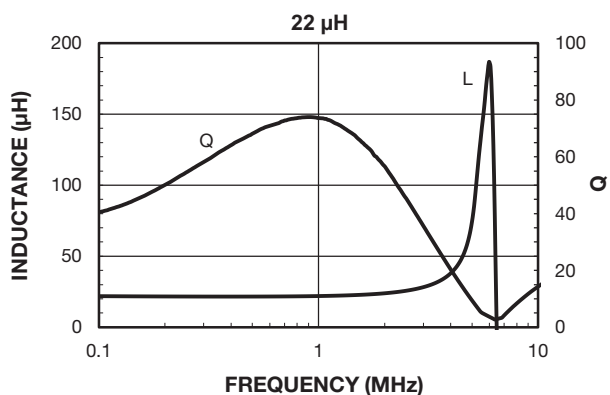
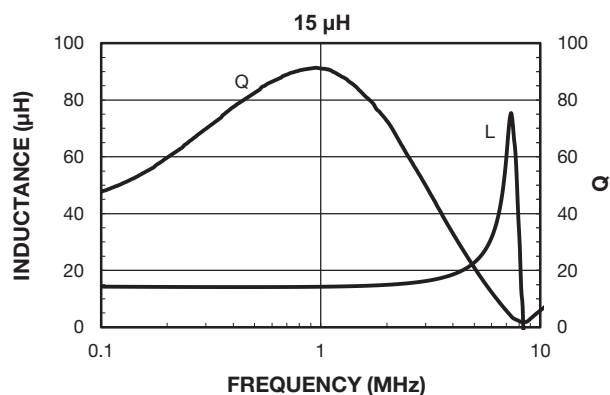
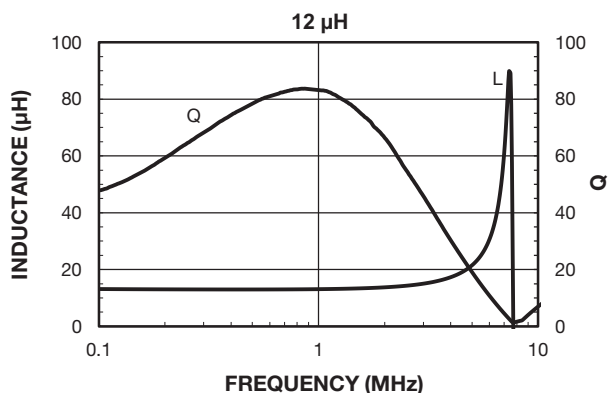
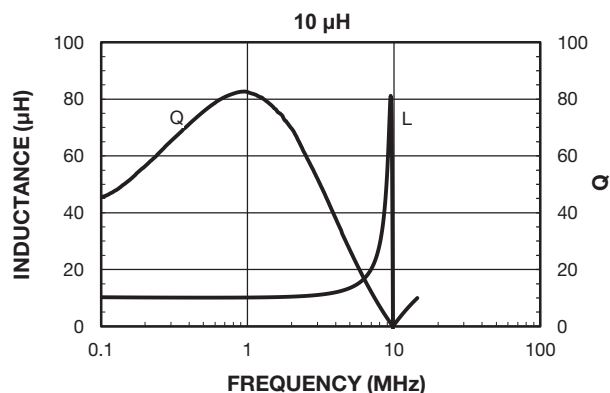
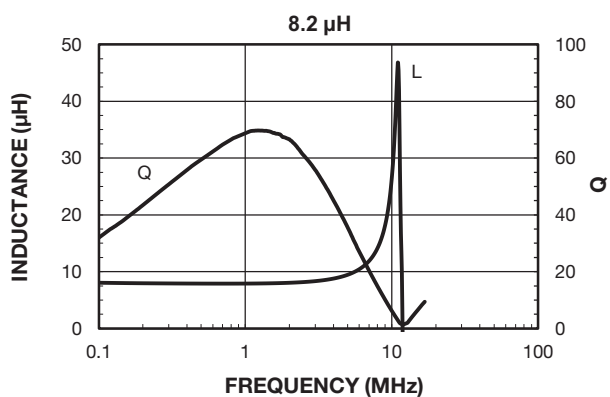
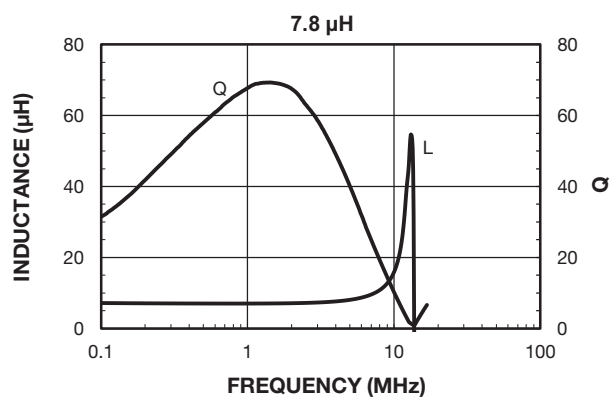
PERFORMANCE GRAPHS: INDUCTANCE AND Q VS. FREQUENCY





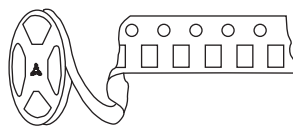
PERFORMANCE GRAPHS: INDUCTANCE AND Q VS. FREQUENCY



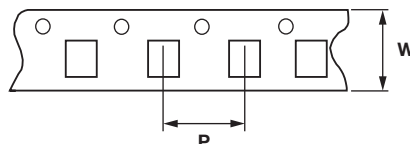
PERFORMANCE GRAPHS: INDUCTANCE AND Q VS. FREQUENCY


SMD Magnetics Packaging Methods

TAPE AND REEL in inches [millimeters] - Meets EIA RS-481 tape and reel packaging standard



User Direction of Feed



Carrier Dimensions

MODEL	PACKAGE CODE			REEL SIZE	CARRIER TAPE WIDTH (W)	COMPONENT PITCH (P)	UNITS/ REEL	PACKAGE CODE			UNITS/ BULK
	PREVIOUS CODE	GLOBAL CODE LEAD (Pb)-BEARING	GLOBAL CODE LEAD (Pb)-FREE					PREVIOUS CODE	GLOBAL CODE LEAD (Pb)-BEARING	GLOBAL CODE LEAD (Pb)-FREE	
IHLP-1212ABER	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	3000	-	-	-	-
IHLP-1212ABEV	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	4000	-	-	-	-
IHLP-1212AEER	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	3000	-	-	-	-
IHLP-1212BZER	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	3000	-	-	-	-
IHLP-1212BZEV	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	4000	-	-	-	-
IHLP-1616AB	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	4000	-	-	EB	100
IHLP-1616BZ	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	4000	-	-	EB	100
IHLP-2020AB	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	4000	-	-	EB	100
IHLP-2020BZ	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	2000	-	-	EB	100
IHLP-2020CZ	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	2000	-	-	EB	100
IHLP-2525AH	-	-	ER	13	0.630 [16.0]	0.315 [8.0]	2000	-	-	EB	100
IHLP-2525BD	-	-	ER	13	0.630 [16.0]	0.315 [8.0]	2000	-	-	EB	100
IHLP-2525CZ	-	-	ER	13	0.630 [16.0]	0.315 [8.0]	2000	-	-	EB	100
IHLP-2525EZ	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	500	-	-	EB	100
IHLP-3232CZ	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	1000	-	-	EB	100
IHLP-3232DZ	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	500	-	-	EB	100
IHLP-4040DZ	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	500	-	-	EB	100
IHLP-5050CE	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	500	-	-	EB	100
IHLP-5050EZ	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	250	-	-	EB	100
IHLP-5050FD	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	250	-	-	EB	100
IHLP-6767DZ	-	-	ER	13	0.945 [24.0]	0.945 [24.0]	250	-	-	EB	100
IHLP-6767GZ	-	-	ER	13	0.945 [24.0]	0.945 [24.0]	200	-	-	EB	100
IHLP-8787MZ	-	-	ER	13	1.73 [44.0]	1.26 [32.0]	100	-	-	-	-
IHCL-4040DZ	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	500	-	-	EB	100
IHLD-4032KB	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	250	-	-	EB	100
IHLD-3232HB	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	250	-	-	EB	100
IHLE-2525CD	-	-	ER	13	0.630 [16.0]	0.315 [8.0]	2000	-	-	EB	100
IHLE-3232DD	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	500	-	-	EB	100
IHLE-4040DD	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	500	-	-	EB	100
IHLR-4040DZ	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	500	-	-	EB	100
IHLM-2525CZ	-	-	ER	13	0.630 [16.0]	0.315 [8.0]	2000	-	-	EB	100
IHLW-4040CF	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	500	-	-	EB	100
IHLW-5050CE	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	500	-	-	EB	100
IFLP-4040DZ	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	500	-	-	EB	100
IFLR-2727EZ	-	-	ER	13	0.630 [16.0]	0.630 [16.0]	1000	-	-	-	-
IFLR-4027EZ	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	1000	-	-	-	-
IFLR-4031GC	-	-	ER	13	0.945 [24.0]	0.472 [12.0]	500	-	-	EB	100
IFLR-5151HZ	-	-	ER	13	0.945 [24.0]	0.630 [16.0]	450	-	-	EB	100

**TAPE AND REEL** in inches [millimeters] - Meets EIA RS-481 tape and reel packaging standard

MODEL	PACKAGE CODE			REEL SIZE	CARRIER TAPE WIDTH (W)	COMPONENT PITCH (P)	UNITS/ REEL	PACKAGE CODE			UNITS/ BULK
	PREVIOUS CODE	GLOBAL CODE LEAD (Pb)- BEARING	GLOBAL CODE LEAD (Pb)-FREE					PREVIOUS CODE	GLOBAL CODE LEAD (Pb)- BEARING	GLOBAL CODE LEAD (Pb)-FREE	
IFSC-0806AZ	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	2000	-	-	-	-
IFSC-1008AB	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	2000	-	-	-	-
IFSC-1111AZ	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	2000	-	-	-	-
IFSC-1111AB	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	2000	-	-	-	-
IFSC-1515AH	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	2000	-	-	-	-
IHHP-0806AZ-01	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	2000	-	-	-	-
IHHP-0806AB-01	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	2000	-	-	-	-
IHHP-1008AZ-01	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	3000	-	-	-	-
IHHP-1008AB-01	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	3000	-	-	-	-
IHHP-1212ZH-01	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	3000	-	-	-	-
IHHP-1212AZ-01	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	3000	-	-	-	-
IHSM-3825	RC2	RE	ER	13	0.945 [24.0]	0.472 [12.0]	750	P09	PJ	EB	100
IHSM-4825	RC2	RE	ER	13	0.945 [24.0]	0.472 [12.0]	750	P09	PJ	EB	100
IHSM-5832	RC3	RF	ER	13	1.26 [32.0]	0.472 [12.0]	500	P09	PJ	EB	100
IHSM-7832	RC4	RG	ER	13	1.73 [44.0]	0.472 [12.0]	500	P09	PJ	EB	100
IDC-2512	-	-	ER	13	0.630 [16.0]	0.315 [8.0]	2000	-	-	-	-
IDC-5020	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	500	-	-	-	-
IDC-7328	-	-	ER	13	0.945 [24.0]	0.945 [24.0]	250	-	-	-	-
IDCS-2512	-	-	ER	13	0.630 [16.0]	0.315 [8.0]	2000	-	-	-	-
IDCS-5020	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	500	-	-	-	-
IDCS-7328	-	-	ER	13	0.945 [24.0]	0.945 [24.0]	250	-	-	-	-
IDCP-1813	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	2000	-	-	-	-
IDCP-2218	-	-	ER	13	0.472 [12.0]	0.315 [8.0]	1500	-	-	-	-
IDCP-3114	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	1000	-	-	-	-
IDCP-3020	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	1000	-	-	-	-
IDCP-3722	-	-	ER	13	0.945 [24.0]	0.472 [12.0]	500	-	-	-	-
IDCP-3916	-	-	ER	13	0.945 [24.0]	0.472 [12.0]	500	-	-	-	-
IFCB-0402	-	-	ER	7	0.315 [8.0]	0.079 [2.0]	10 000	-	-	-	-
ILC-0402	-	-	ER	7	0.315 [8.0]	0.079 [2.0]	10 000	-	-	-	-
ILC-0603	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	4000	-	-	-	-
ILC-0805	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	4000	-	-	-	-
IMC-0402	-	-	ER	7	0.315 [8.0]	0.079 [2.0]	10 000	-	-	-	-
IMC-0402-01	-	-	ER	7	0.315 [8.0]	0.079 [2.0]	10 000	-	-	-	-
IMC-0603	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	4000	-	-	-	-
IMC-0603-01	-	-	ER	7	0.315 [8.0]	0.079 [2.0]	3000	-	-	-	-
IMC-0805-01	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	2000	-	-	-	-
IMC-1008	-	-	ER	7	0.315 [8.0]	0.157 [4.0]	2000	-	-	-	-
IMC-1210	R98/RB3 R99/RB4	SY/AN SZ/R9	ER/ET ES/EU	7	0.315 [8.0]	0.157 [4.0]	2000	B13	BN	EB	500
				13	0.315 [8.0]	0.157 [4.0]	7500				
IMC-1210-100	R98/RB3 R99/RB4	SY/AN SZ/R9	ER/ET ES/EU	7	0.315 [8.0]	0.157 [4.0]	2000	B13	BN	EB	500
				13	0.315 [8.0]	0.157 [4.0]	7500				
IMC-1812	R73/R92 R13/R91	RV/RX RQ/RW	ER/ET ES/EU	7	0.472 [12.0]	0.315 [8.0]	500	B13	BN	EB	500
				13	0.472 [12.0]	0.315 [8.0]	2000				
IMCH-1812	-	-	ER	7	0.472 [12.0]	0.315 [8.0]	500	-	-	-	-
IMC-2220	-	-	ER	13	0.630 [16.0]	0.472 [12.0]	1000	-	-	-	-

IHLP PACKAGING

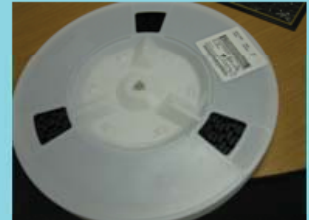
COMPONENT PHOTO



POCKET TAPE PHOTO



REEL PHOTO



CONTAINER PHOTO

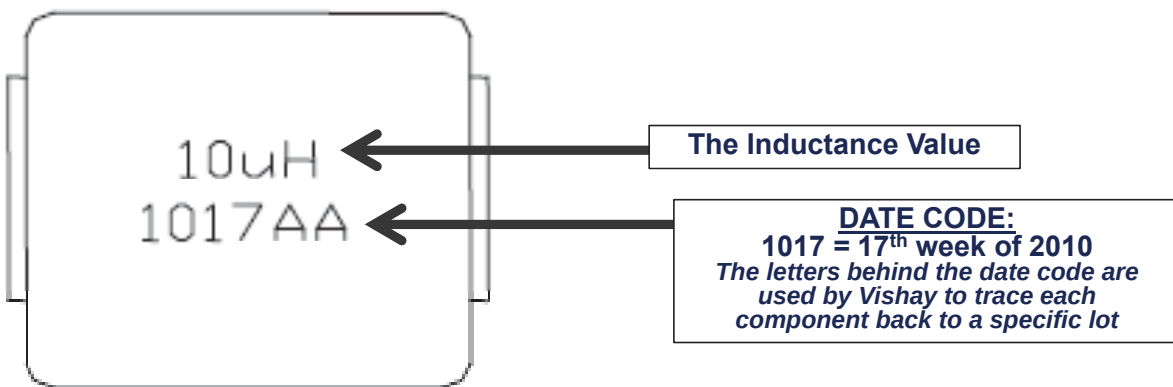


UNIT LOAD PHOTO





IHLP COMPONENT PRINT





Production Part Approval Process

The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements

Cross-Section IHLP-5050FD - - - - -





Production Part Approval Process

The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements

Example Photos of IHLP Welds

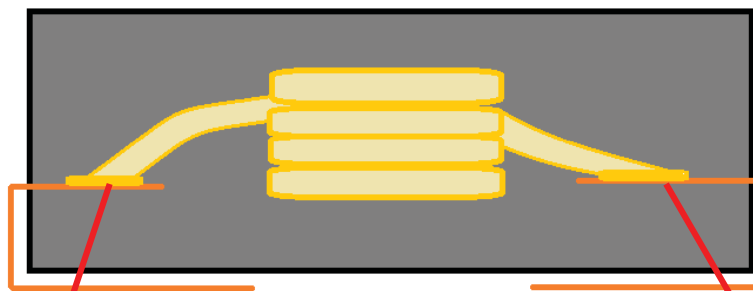




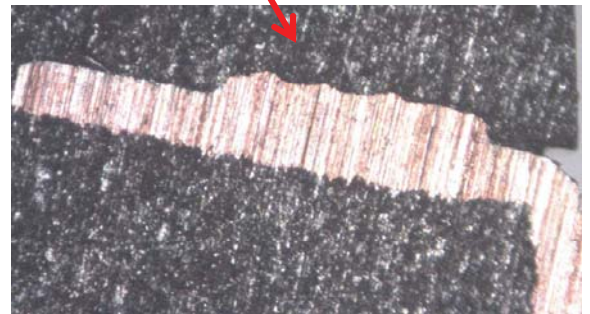
Production Part Approval Process

The following PPAP documentation is assembled according to
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Cross sectional Photos of IHLP Welds



Inter-Metallic
bonding
between the
wire and
Leadframe



Production Part Approval Process

**The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements**

Use the control buttons below to navigate through the PPAP sections.

Section 2: Engineering Change Documents

There are no applicable Engineering Change Documents for this part number.

Vishay / Dale Electronics

1505 East Hwy 50 Yankton, SD 57078, USA Phone (605) 665-9301 Fax (605) 668-4247

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Production Part Approval Process

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Use the control buttons below to navigate through the PPAP sections.

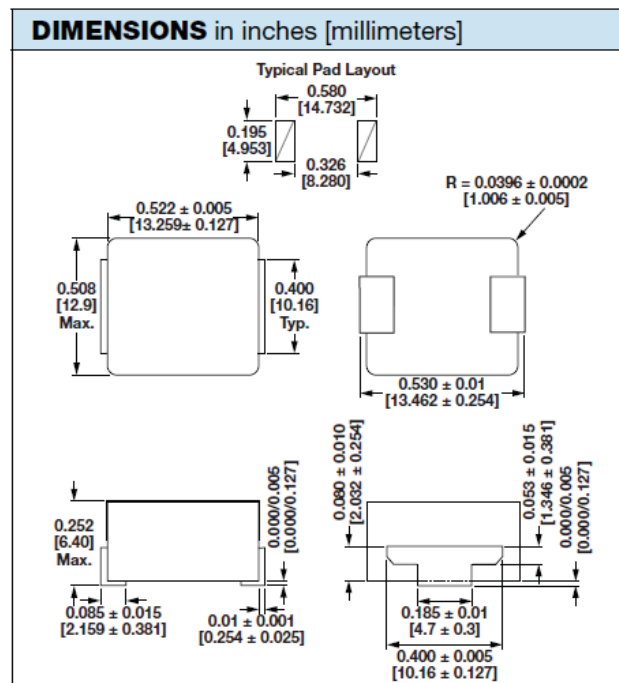
Section 3: Customer Engineering Approval

Customer Engineering Approval does not apply for this part number

Production Part Approval Process

The following PPAP documentation is assembled according to
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DIMENSIONAL ANALYSIS IHLP5050FD-5A





Production Part Approval Process

The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements

DIMENSIONAL ANALYSIS IHLP5050FD-5A

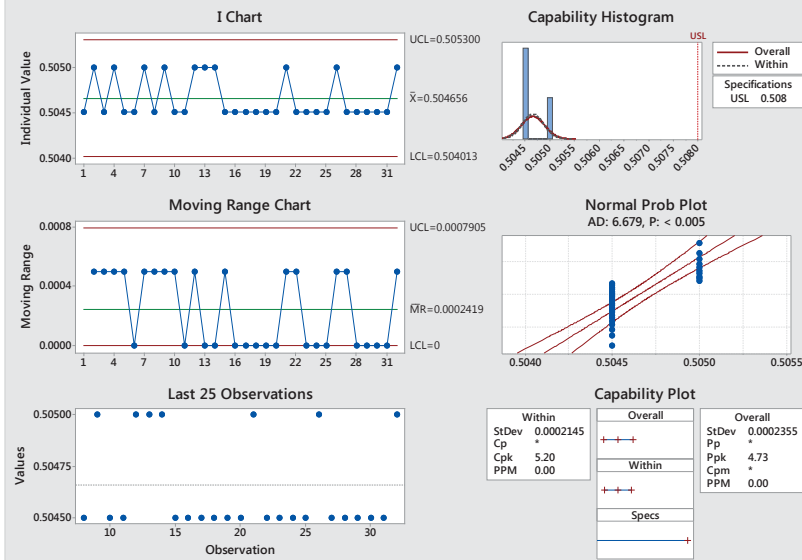
	Width (.508"Max)	Length (.520-.540")	Height (.252"max)	tab length (.070-.100")	Tab Width (.185+/- .01")
1	0.5045	0.5285	0.2465	0.083	0.185
2	0.505	0.5285	0.246	0.081	0.185
3	0.5045	0.5285	0.247	0.086	0.185
4	0.505	0.53	0.2465	0.084	0.185
5	0.5045	0.53	0.247	0.089	0.185
6	0.5045	0.5305	0.247	0.086	0.185
7	0.5045	0.5285	0.2475	0.085	0.185
8	0.505	0.531	0.247	0.084	0.185
9	0.5045	0.528	0.246	0.087	0.185
10	0.505	0.5315	0.2465	0.086	0.185
11	0.5045	0.5295	0.247	0.082	0.185
12	0.5045	0.529	0.247	0.084	0.185
13	0.505	0.531	0.2475	0.083	0.185
14	0.505	0.5305	0.247	0.086	0.185
15	0.505	0.5295	0.247	0.084	0.185
16	0.5045	0.5285	0.247	0.089	0.185
17	0.5045	0.5295	0.2455	0.084	0.185
18	0.5045	0.5295	0.2475	0.083	0.185
19	0.5045	0.5285	0.2465	0.085	0.185
20	0.5045	0.5285	0.2465	0.086	0.185
21	0.505	0.5295	0.2475	0.089	0.185
22	0.5045	0.5295	0.2465	0.089	0.185
23	0.5045	0.529	0.246	0.084	0.185
24	0.5045	0.53	0.246	0.082	0.185
25	0.5045	0.529	0.247	0.081	0.185
26	0.505	0.5285	0.2475	0.081	0.185
27	0.5045	0.5295	0.247	0.086	0.185
28	0.5045	0.5305	0.2475	0.086	0.185
29	0.5045	0.5285	0.2465	0.085	0.185
30	0.5045	0.528	0.2475	0.084	0.185
31	0.5045	0.531	0.247	0.083	0.185
32	0.505	0.528	0.2465	0.089	0.185

Production Part Approval Process

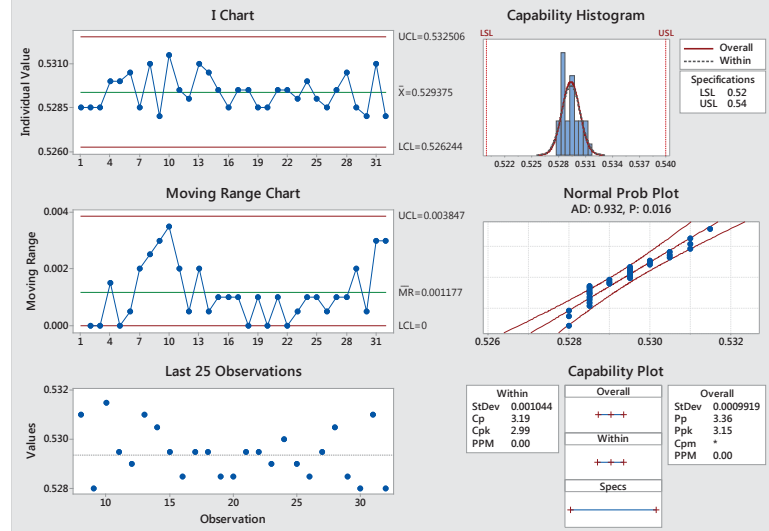
The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements

DIMENSIONAL ANALYSIS IHLP5050FD-5A

Process Capability Sixpack of Width (.508 Max)



Process Capability Sixpack of Length (.520-.540)

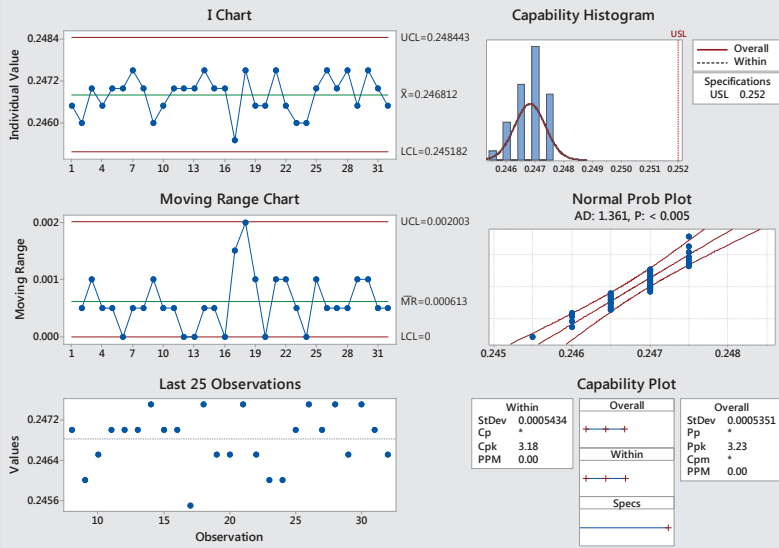


Production Part Approval Process

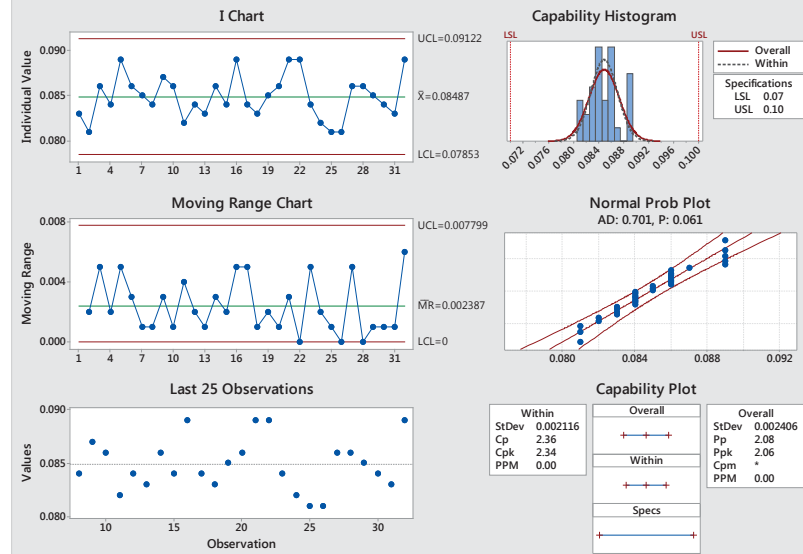
The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements

DIMENSIONAL ANALYSIS IHLP5050FD-5A

Process Capability Sixpack of Height (.252max)



Process Capability Sixpack of tab length (.085+/- .015")





TEST RESULTS FOR IHLP5050FD-5A FROM DANSHUI CHINA

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IHLP5050FDER330M5A TEST DATA

- This data represents parts manufactured in the Danshui, China manufacturing facility.



IHLP5050FDER330M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas Temp							
0	3X Reflow Preconditioning for lead-free products	ICP-10,373	As specified in sections 6.3 thru 6.4 in ICP-10,373										
1	Pre- and Post-Stress Electrical Test	IHLP Data Sheet	L (uH) – 100KHz and 250mV DCR – 25°C Ambient	L=±15% of initial, DCR =±15% of initial	All tests requiring electrical data								
3	High Temp Exposure	IEC-60068 Part 2-2 test group BA	155C for 2000 hours, unpow er ed readings at 0, 250, 500, 1000 and 2000 hour intervals. Initial (0 hr.) and final (2000 hr.) readings at LT/RT/HT LT=Low Temperature=-55°C, RT=Room Temperature=+25°C,HT= High Temperature=+125°C for –A1/1A models. HT=High Temperature =+155° C for -5A models.	L=±20% of initial, DCR =±20% of initial	77			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	31.961	33.624	7.082	33.490	33.670	1.934
							Mimimum	26.746	28.320	5.077	32.190	32.620	-0.390
							Mean	28.591	30.162	5.497	32.787	33.093	0.937
							Std Dev	1.059	1.097	0.293	0.267	0.223	0.489
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	32.186	33.849	7.150	48.730	48.320	0.864
							Mimimum	26.925	28.515	5.021	47.040	47.010	-1.195
							Mean	28.788	30.367	5.488	47.759	47.584	-0.365
							Std Dev	1.070	1.100	0.313	0.320	0.286	0.438
						+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	32.384	34.574	7.835	72.310	72.520	1.765
							Mimimum	27.119	28.985	6.239	69.630	69.980	-1.525
							Mean	28.963	30.906	6.708	70.745	71.035	0.413
							Std Dev	1.079	1.152	0.293	0.534	0.513	0.662



IHLP5050FDER330M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas Temp							
	Low Temperature Storage	EC-60068 Part 2-1 test group Aa	-55°C for 2000 hours unpowered readings at 0, 250, 500, 1000 and 2000 hour intervals. Initial (0 hr.) and final (2000 hr.) readings at LT/RT/H	L = $\pm 20\%$ of initial, DCR = $\pm 20\%$ of initial	77	-55 deg. C	Inductance (μ H)			DC Resistance ($m\Omega$)			
								Initial	Final	% Δ	Initial	Final	% Δ
							Maximum	30.933	31.119	1.265	33.530	33.720	4.116
							Minimum	26.425	26.641	0.240	32.020	32.610	-0.484
							Mean	28.372	28.616	0.863	32.595	33.145	1.695
							Std Dev	1.040	1.026	0.153	0.337	0.289	0.940
						+25 deg. C		Initial	Final	% Δ	Initial	Final	% Δ
							Maximum	31.141	31.292	1.136	48.290	48.460	1.431
							Minimum	26.623	26.807	0.462	46.720	46.990	-0.127
							Mean	28.582	28.795	0.746	47.322	47.636	0.664
							Std Dev	1.051	1.040	0.129	0.353	0.345	0.350
						+155 deg. C		Initial	Final	% Δ	Initial	Final	% Δ
							Maximum	31.362	31.398	0.367	71.400	71.760	2.349
							Minimum	26.897	26.853	-0.206	68.890	69.270	-1.919
							Mean	28.819	28.853	0.117	70.015	70.511	0.713
							Std Dev	1.041	1.045	0.122	0.564	0.579	0.810



IHLP5050FDER330M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas Temp							
4	Temperature Cycling	IEC-60068, Part 2.14 test group Na	-55°C to +125°C (+155° C for -5A models) dwell time = 30 min. transfer time ≤10 sec. no. of cycles = 1000 unpowered initial (0 cycles) and final 1000 cycles). Readings at LT/RT/HT	L=±20% of initial, DCR = ±20% of initial	77			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	30.546	31.126	2.645	34.090	33.430	4.607
							Mimimum	26.623	27.223	1.666	31.690	32.290	-3.403
							Mean	28.437	29.039	2.117	33.175	32.789	-1.157
							Std Dev	0.996	0.998	0.205	0.344	0.253	0.993
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	30.764	31.311	2.534	48.780	48.490	0.667
							Mimimum	26.805	27.394	1.460	46.910	46.980	-1.497
							Mean	28.623	29.200	2.016	47.717	47.670	-0.098
							Std Dev	1.007	1.003	0.226	0.369	0.362	0.421
						+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	30.943	31.631	2.874	72.500	72.770	0.977
							Mimimum	27.032	27.645	1.956	70.030	69.850	-1.139
							Mean	28.829	29.511	2.366	71.107	71.181	0.103
							Std Dev	0.994	1.032	0.182	0.586	0.662	0.372



IHLP5050FDER330M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas Temp							
7	Biased Humidity	IEC-60068 Part 2-67	temperature = 85°C ±20°C Humidity = 85% ±5% RH Duration = 1000 hours Power = No Power Initial (0hr.) and final (1000hr.) readings at LT/RT/HT	L= ±20% of initial, DCR = ±20% of initial	77			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	31.971	32.208	1.021	33.860	34.010	1.704
							Mimimum	26.189	26.248	-0.578	32.410	32.690	-0.091
							Mean	28.613	28.734	0.422	32.972	33.260	0.874
							Std Dev	1.168	1.193	0.285	0.334	0.338	0.498
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	32.226	32.373	1.054	49.560	48.630	-0.273
							Mimimum	26.406	26.426	-0.774	47.630	47.020	-2.431
							Mean	28.834	28.920	0.298	48.403	47.773	-1.301
							Std Dev	1.191	1.200	0.310	0.419	0.401	0.394
						+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	32.456	32.579	0.598	72.380	72.760	0.971
							Mimimum	26.588	26.607	-0.949	69.930	69.890	-0.399
							Mean	28.999	29.061	0.209	71.021	71.182	0.226
							Std Dev	1.190	1.207	0.232	0.610	0.667	0.249



IHLP5050FDER330M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas Temp							
8	Operational Life	MIL-STD-202, Method 108A	Temperature = 85°C for -1A/A1 models. Temperature =115° C for 5A models. Duration = 2000hrs. Pow er = As noted on the test request. Readings a 0, 250, 500, 1000 and 2000 hour intervals. Initial (0 hr.) and final (2000 hr.) readings at LT/RT/HT	L=±20% of initial, DCR = ±20% of initial	77			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	30.558	33.216	11.273	34.340	33.930	1.133
							Mimimum	26.515	28.445	4.495	32.570	32.250	-3.441
							Mean	28.442	30.847	8.466	33.229	32.946	-0.848
							Std Dev	0.993	1.062	1.334	0.332	0.371	0.927
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	30.773	33.548	11.587	48.700	49.060	1.162
							Mimimum	26.664	29.070	5.520	47.090	46.710	-0.976
							Mean	28.639	31.158	8.806	47.885	47.923	0.079
						Std Dev	0.997	1.055	1.275	0.367	0.485	0.595	
						+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	30.984	34.239	12.436	73.100	72.700	1.907
							Mimimum	26.948	29.609	6.353	69.630	69.770	-1.649
							Mean	28.871	31.685	9.756	71.276	71.199	-0.103
						Std Dev	0.991	1.084	1.298	0.741	0.633	0.742	



IHLP5050FDER330M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas Temp						
9	External Visual	MIL-STD-883G Method 2009.9	Inspect construction and workmanship.	Pass all criteria as defined in DPS-11,865 VA1	All	na	Pass					
10	Physical Dimensions	JESD22 Method JB-100	Verify physical dimensions per part specification	All parts within dimensional tolerance per data sheet	30	na	Pass					
12	Resistance to Solvents	MIL-STD-202G Method 215K	Add Aqueous wash chemical. OKEM Clean or equivalent. Do not use banned solvents.	Pass all criteria as defined in DPS-11,865 VA1 $L = \pm 20\%$ of initial, $DCR = \pm 20\%$ of initial	5	na	Pass					



IHLP5050FDER330M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas Temp							
13	Mechanical Shock	IEC-60068 part 2.27 test group Ea with precondition per 0 above	Pulse Shape-Half Sine Normal Pulse Length 6ms Peak acceleration-100g No. shocks-6 each in both directions of each axis (total of 36) Initial and final readings at LT/RT/HT	L=±20% of initial, DCR =±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	31.352	31.562	0.980	33.680	33.890	1.369
							Mimimum	27.374	27.519	0.435	32.880	32.920	-0.448
							Mean	28.658	28.866	0.726	33.255	33.355	0.301
							Std Dev	1.014	1.015	0.124	0.203	0.223	0.441
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	31.547	31.785	1.021	49.240	47.990	-1.501
							Mimimum	27.547	27.696	0.511	47.980	47.010	-2.558
							Mean	28.861	29.076	0.747	48.475	47.457	-2.099
						Std Dev	1.032	1.036	0.113	0.291	0.229	0.292	
						+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	31.683	31.757	0.257	72.220	71.840	-0.085
							Mimimum	27.562	27.622	0.146	70.470	70.410	-1.193
							Mean	28.977	29.039	0.212	71.414	71.119	-0.413
						Std Dev	1.036	1.040	0.030	0.436	0.399	0.220	



IHLP5050FDER330M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas Temp							
14	Vibration	IEC-60068 PART 2-6 TEST GROUP Fc. With precondition per 0 above	Pulse Shape-sine wave range of frequency 1 10-55Hz. Amplitude ±0.75mm Range of frequency 2 55-2000Hz Amplitude; 10G Frequency Sweep: 1 oct./min. Duration: 24 h each of 3 axis. Initial and final readings at LT/RT/HT	L=±20% of initial, DCR =±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	30.104	30.303	1.501	33.980	33.950	0.451
							Mimimum	26.861	27.092	0.662	32.800	32.580	-1.107
							Mean	28.246	28.521	0.975	33.342	33.213	-0.390
							Std Dev	0.922	0.919	0.152	0.309	0.401	0.491
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	30.343	30.583	1.286	48.960	48.860	0.248
							Mimimum	27.028	27.326	0.792	47.600	47.460	-1.070
							Mean	28.449	28.725	0.973	48.297	48.094	-0.419
						Std Dev	0.925	0.921	0.119	0.375	0.354	0.323	
						+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	30.521	30.556	0.301	72.050	71.630	-0.209
							Mimimum	27.212	27.258	-0.117	70.350	69.590	-1.292
							Mean	28.635	28.682	0.164	71.074	70.567	-0.712
							Std Dev	0.910	0.915	0.069	0.470	0.522	0.332



IHLP5050FDER330M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas Temp							
	Bump	IEC-60068 part 2-29 test group Eb with precondition per 0 above.	Pulse shape: half sine Nominal pulse length: 6 ms Peak Acceleration: 40g No. of shocks: 4000 each mechanical axis. Initial and final readings at LT/RT/HT	L=±20% of initial, DCR =±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	30.228	30.394	1.059	33.540	33.610	0.934
							Mimimum	26.811	27.095	0.549	32.990	33.030	-1.073
							Mean	28.297	28.527	0.810	33.223	33.297	0.223
							Std Dev	0.727	0.725	0.107	0.169	0.171	0.531
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	30.502	30.718	1.078	47.860	48.710	2.062
							Mimimum	26.959	27.249	0.709	47.050	47.920	1.482
							Mean	28.489	28.733	0.859	47.414	48.248	1.758
							Std Dev	0.742	0.742	0.099	0.213	0.218	0.142
						+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	30.703	30.724	0.136	71.590	72.090	2.413
							Mimimum	27.185	27.208	0.054	69.610	70.850	0.056
							Mean	28.666	28.690	0.085	70.589	71.374	1.114
							Std Dev	0.735	0.736	0.022	0.418	0.305	0.515



IHLP5050FDER330M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas Temp							
15	Resistance to Solder Heat	MIL-STD-202G Method 210F Condition K	IR/convection reflow. 250 $\pm$ 5°C for 30 $\pm$ 5sec. Ramp rate 1°C/s to 4°C/; Above 183°C for 90s-120s	L= $\pm$ 20% of initial, DCR = $\pm$ 20% of initial	30		Inductance (μ H)			DC Resistance (m Ω)			
							Initial	Final	% Δ	Initial	Final	% Δ	
							Maximum	29.770	30.208	1.913	48.580	48.510	0.042
							Minimum	27.154	27.563	0.889	47.840	47.790	-0.270
							Mean	28.138	28.529	1.394	48.121	48.043	-0.163
17	ESD	AEC-Q200-002	Determine the Classification of the part.	L= $\pm$ 20% of initial, DCR = $\pm$ 20% of initial	15	+25 deg. C	Std Dev	0.673	0.668	0.219	0.179	0.174	0.061
							Inductance (μ H)			DC Resistance (m Ω)			
							Initial	25KV	% Δ	Initial	25KV	% Δ	
							Maximum	32.782	30.501	-6.587	48.410	48.400	0.166
							Minimum	29.777	27.637	-7.739	47.800	47.810	-0.208
18	Solderability	J-STD-002C Method B1	4 hours @ 155°C dry heat @ 255°C. 90° dipping angle.	95% or greater coverage on "A" (seating plane) per J-STD-002C	15	NA	Mean	31.123	28.934	-7.034	48.073	48.097	0.050
							Std Dev	0.845	0.826	0.310	0.188	0.183	0.103
							Pass						



IHLP5050FDER330M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas Temp													
19	Electrical Characterization	User Specification	Min, Max, Mean, and Standard Deviation @ Min (-55C), Room, and Max (+125C) operating temperatures. After mounted, allow +/- 5% shift DCR at room temp. - 55C/+125C DCR Max calculated using temp conversion for copper: $R_2 = [(T_2 + 234.5) / (234.5 + T_A)] * 1.05R_A$ (A = Ambient, 2 = new con)	Final Test: L= ±20% of initial, DCR per calculated limits described in test conditions. L test for -55C & +125C = ±20% initial	30			Inductance (μH)			DC Resistance (mΩ)								
								Initial			Initial								
						-55 deg. C	Maximum	30.933		33.530									
							Mimimum	26.425		32.020									
							Mean	28.372		32.595									
							Std Dev	1.040		0.337									
						+25 deg. C		Initial		Initial									
							Maximum	31.141		48.290									
							Mimimum	26.623		46.720									
							Mean	28.582		47.322									
						+155 deg. C	Std Dev	1.051		0.353									
								Initial		Initial									
							Maximum	31.362		71.400									
							Mimimum	26.897		68.890									
						Mean	28.819		70.015										
							Std Dev	1.041		0.564									
21	Board Flex	AEC-Q200-005 Appendix 2	2mm minimum flex for 60 (+5) sec	Pass all criteria as defined in DPS-11,865 VA1 L= ±20% of initial, DCR = ±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)								
								Initial	Final	%Δ	Initial	Final	%Δ						
						+25 deg. C	Maximum	30.787	30.985	0.642	48.740	48.740	0.145						
							Mimimum	26.407	26.540	0.319	48.050	48.060	-0.228						
							Mean	28.288	28.425	0.482	48.337	48.326	-0.023						
							Std Dev	0.968	0.981	0.089	0.194	0.190	0.084						
						22	Terminal Strength	AEC-Q200-006 Appendix 1	Force of 1.8kg (17.7 N) for 60 seconds	Pass all criteria as defined in DPS-11,865 VA1 L= ±20% of initial, DCR = ±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)		
														Initial	Final	%Δ	Initial	Final	%Δ
+25 deg. C	Maximum	30.686	30.834	0.635	48.540							48.500	0.692						
	Mimimum	26.928	27.033	-0.259	47.680							47.840	-0.536						
	Mean	28.717	28.799	0.288	48.087							48.122	0.073						
	Std Dev	1.041	1.042	0.240	0.243							0.200	0.233						



BeerSheva, Israel manufacturing facility





IHLP5050FDER560M5A TEST RESULTS

- This data represents parts manufactured in the Beer'Sheva, Israel manufacturing facility.

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IHLP5050FDER560M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas. Temp.							
	Low Temperature Storage	EC-60068 Part 2-1 test group Aa	-55°C for 2000 hours unpow er ed readings at 0, 250, 500, 1000 and 2000 hour intervals. Initial (0 hr.) and final (2000 hr.) readings at LT/RT/H	L=±20% of initial, DCR =±20% of initial	77			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	54.166	54.278	0.578	64.840	64.320	0.390
							Mimimum	45.169	45.313	-1.964	62.960	62.410	-1.670
							Mean	50.288	50.425	0.274	63.605	63.323	-0.442
							Std Dev	1.968	1.949	0.284	0.372	0.351	0.351
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	54.253	54.674	1.135	92.710	93.280	0.857
							Mimimum	45.102	45.489	-2.595	91.000	91.290	-0.879
							Mean	50.315	50.699	0.764	91.975	92.339	0.396
							Std Dev	2.021	2.028	0.409	0.369	0.410	0.290
						+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	54.717	54.736	0.340	129.440	129.410	0.616
							Mimimum	45.523	45.542	-2.585	126.440	124.830	-2.301
							Mean	50.733	50.745	0.024	127.986	127.713	-0.213
							Std Dev	2.060	2.057	0.315	0.697	0.831	0.367



IHLP5050FDER560M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas. Temp.							
4	Temperature Cycling	IEC-60068, Part 2.14 test group Na	-55°C to +125°C (+155° C for -5A models) dw ell time = 30 min. transfer time ≤10 sec. no. of cycles = 1000 unpowered initial (0 cycles) and final 1000 cycles). Readings at LT/RT/HT	L= ±20% of initial, DCR = ±20% of initial	77			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	55.959	56.775	2.329	64.100	65.080	2.468
							Minimum	46.788	47.853	1.123	62.770	63.350	0.651
							Mean	50.411	51.311	1.711	63.391	64.224	1.316
							Std Dev	2.148	2.078	0.239	0.341	0.468	0.507
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	56.176	57.124	2.771	92.840	92.860	2.422
							Minimum	46.723	48.017	1.279	91.310	91.410	-0.293
							Mean	50.424	51.526	2.116	92.160	92.216	1.061
							Std Dev	2.197	2.122	0.295	0.344	0.336	0.175
						+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	56.691	57.979	2.641	139.140	139.840	2.415
							Minimum	47.105	48.327	1.832	135.240	137.630	0.072
							Mean	50.842	52.035	2.266	137.370	138.878	1.100
							Std Dev	2.241	2.260	0.197	0.890	0.623	0.582



IHLP5050FDER560M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas. Temp.							
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7	Biased Humidity	IEC-60068 Part 2-67	temperature = 85°C ±20°C Humidity = 85% ±5% RH Duration = 1000 hours Power = No Power Initial (0hr.) and final (1000hr.) readings at LT/RT/HT	L= ±20% of initial, DCR = ±20% of initial	77			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	55.612	55.708	0.636	64.940	64.460	-0.331
							Mimimum	46.839	46.846	0.016	63.030	62.370	-1.983
							Mean	50.531	50.680	0.294	63.770	63.183	-0.918
							Std Dev	2.108	2.133	0.117	0.449	0.414	0.326
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	55.609	56.068	1.236	93.130	92.570	0.196
							Mimimum	46.893	47.128	0.461	91.520	90.490	-1.958
							Mean	50.557	50.979	0.834	92.258	91.666	-0.642
							Std Dev	2.159	2.170	0.142	0.333	0.522	0.514
						+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	56.101	56.416	0.962	129.870	128.080	-0.300
							Mimimum	47.106	47.324	0.018	126.390	123.500	-3.754
							Mean	50.957	51.234	0.544	128.133	126.369	-1.376
							Std Dev	2.201	2.214	0.128	0.733	1.016	0.657



IHLP5050FDER560M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas. Temp.							
8	Operational Life	MIL-STD-202, Method 108A	Temperature = 85°C for -1A/A1 models. Temperature =115° C for 5A models. Duration = 2000hrs. Power = As noted on the test request. Readings a 0, 250, 500, 1000 and 2000 hour intervals. Initial (0 hr.) and final (2000 hr.) readings at LT/RT/HT	L=±20% of initial, DCR = ±20% of initial	77			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	55.334	59.851	11.861	65.130	64.390	-0.473
							Mimimum	45.909	49.447	4.378	63.140	62.370	-1.487
							Mean	50.014	53.619	7.242	63.760	63.124	-0.996
							Std Dev	2.248	2.178	1.816	0.483	0.484	0.245
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	55.551	60.470	12.641	93.080	92.840	0.033
							Mimimum	45.942	49.840	5.286	91.730	91.030	-0.925
							Mean	50.053	54.139	8.199	92.252	91.884	-0.399
						Std Dev	2.294	2.228	1.694	0.308	0.371	0.229	
						+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	56.071	61.388	12.584	129.780	128.780	-0.204
							Mimimum	46.340	50.131	5.519	125.720	124.880	-1.017
							Mean	50.436	54.623	8.332	127.824	127.154	-0.523
						Std Dev	2.323	2.318	1.719	0.791	0.741	0.181	



IHLP5050FDER560M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas. Temp.						
9	External Visual	MIL-STD-883G Method 2009.9	Inspect construction and workmanship.	Pass all criteria as defined in DPS-11,865 VA1	All	na	Pass					
10	Physical Dimensions	JESD22 Method JB-100	Verify physical dimensions per part specification	All parts within dimensional tolerance per data sheet	30	na	Pass					
12	Resistance to Solvents	MIL-STD-202G Method 215K	Add Aqueous wash chemical. OKEM Clean or equivalent. Do not use banned solvents.	Pass all criteria as defined in DPS-11,865 VA1 $L = \pm 20\%$ of initial, $DCR = \pm 20\%$ of initial	5	na	Pass					



IHLP5050FDER560M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas. Temp.							
13	Mechanical Shock	IEC-60068 part 2.27 test group Ea with precondition per 0 above	Pulse Shape-Half Sine Normal Pulse Length 6ms Peak acceleration-100g No. shocks-6 each in both directions of each axis (total of 36) Initial and final readings at LT/RT/HT	$L = \pm 20\%$ of initial, $DCR = \pm 20\%$ of initial	30	-55 deg. C	Inductance (μ H)			DC Resistance ($m\Omega$)			
								Initial	Final	% Δ	Initial	Final	% Δ
							Maximum	55.291	55.305	1.014	64.100	65.080	2.472
							Minimum	46.013	46.349	0.025	62.770	63.350	0.671
							Mean	50.241	50.544	0.610	63.391	64.224	1.313
							Std Dev	2.323	2.253	0.212	0.341	0.468	0.507
						+25 deg. C		Initial	Final	% Δ	Initial	Final	% Δ
							Maximum	55.349	56.062	1.747	92.860	92.910	0.564
							Minimum	46.011	46.603	1.052	91.500	91.790	-0.140
							Mean	50.238	50.904	1.331	92.176	92.431	0.277
							Std Dev	2.355	2.345	0.149	0.316	0.265	0.161
						+155 deg. C		Initial	Final	% Δ	Initial	Final	% Δ
							Maximum	56.039	56.090	0.463	137.840	138.820	2.878
							Minimum	46.414	46.546	-0.140	134.760	136.220	0.007
							Mean	50.733	50.810	0.153	135.883	137.524	1.210
							Std Dev	2.403	2.394	0.101	0.751	0.711	0.720



IHLP5050FDER560M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas. Temp.							
14	Vibration	IEC-60068 PART 2-6 TEST GROUP Fc. With precondition per 0 above	Pulse Shape-sine wave range of frequency 1 10-55Hz. Amplitude $\pm 0.75\text{mm}$ Range of frequency 2 55-2000Hz Amplitude; 10G Frequency Sweep: 1 oct./min. Duration: 24 h each of 3 axis. Initial and final readings at LT/RT/HT	$L = \pm 20\%$ of initial, DCR $= \pm 20\%$ of initial	30		Inductance (μH)			DC Resistance ($\text{m}\Omega$)			
							Initial	Final	% Δ	Initial	Final	% Δ	
						-55 deg. C	Maximum	56.043	56.206	0.888	64.670	65.020	1.690
							Minimum	47.019	47.436	0.164	62.650	63.430	0.062
							Mean	51.719	51.995	0.536	63.612	64.260	1.022
							Std Dev	2.437	2.405	0.143	0.593	0.409	0.534
						+25 deg. C	Initial	Final	% Δ	Initial	Final	% Δ	
							Maximum	56.153	56.770	1.459	92.970	93.700	1.346
							Minimum	47.075	47.669	0.344	91.440	92.190	0.260
							Mean	51.829	52.401	1.104	92.155	93.023	0.941
							Std Dev	2.475	2.514	0.307	0.350	0.444	0.296
						+155 deg. C	Initial	Final	% Δ	Initial	Final	% Δ	
							Maximum	56.780	56.712	0.196	139.140	139.840	2.415
							Minimum	48.078	48.066	-0.505	135.240	137.630	0.072
							Mean	52.342	52.292	-0.093	137.370	138.878	1.100
							Std Dev	2.520	2.507	0.104	0.890	0.623	0.582



IHLP5050FDER560M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas. Temp.							
	Bump	IEC-60068 part 2-29 test group Eb with precondition per 0 above.	Pulse shape: half sine Nominal pulse length: 6 ms Peak Acceleration: 40g No. of shocks: 4000 each mechanical axis. Initial and final readings at LT/RT/HT	$L = \pm 20\%$ of initial, $DCR = \pm 20\%$ of initial	30		Inductance (μH)			DC Resistance ($m\Omega$)			
							Initial	Final	% Δ	Initial	Final	% Δ	
						-55 deg. C	Maximum	55.671	56.221	1.291	63.500	64.090	1.417
							Minimum	46.725	47.266	0.477	62.670	63.020	0.270
							Mean	50.363	50.820	0.911	63.040	63.523	0.766
							Std Dev	2.055	2.036	0.189	0.233	0.317	0.247
						+25 deg. C	Initial	Final	% Δ	Initial	Final	% Δ	
							Maximum	55.815	56.642	1.760	92.670	93.470	0.863
							Minimum	46.782	47.532	1.059	91.760	92.000	-0.065
							Mean	50.480	51.206	1.442	92.216	92.616	0.433
							Std Dev	2.125	2.119	0.166	0.274	0.386	0.217
						+155 deg. C	Initial	Final	% Δ	Initial	Final	% Δ	
							Maximum	56.547	56.582	0.698	139.140	139.790	1.835
							Minimum	47.256	47.484	-0.161	135.180	137.050	0.065
							Mean	51.041	51.137	0.190	136.836	138.013	0.863
							Std Dev	2.186	2.171	0.159	1.095	0.644	0.492



IHLP5050FDER560M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas. Temp.							
15	Resistance to Solder Heat	MIL-STD-202G Method 210F Condition K	IR/convection reflow. 250 $\pm$ 5°C for 30 $\pm$ 5sec. Ramp rate 1°C/s to 4°C/s; Above 183°C for 90s-120s	L = $\pm$ 20% of initial, DCR = $\pm$ 20% of initial	30		Inductance (μ H)			DC Resistance (m Ω)			
							Initial	Final	% Δ	Initial	Final	% Δ	
							Maximum	56.43	55.89	0.26	93.39	93.07	0.63
							Minimum	47.63	47.65	-1.14	91.87	91.83	-0.72
							Mean	50.41	50.24	-0.32	92.53	92.35	-0.19
17	ESD	AEC-Q200-002	Determine the Classification of the part.	L = $\pm$ 20% of initial, DCR = $\pm$ 20% of initial	15		Inductance (μ H)			DC Resistance (m Ω)			
							Initial	4KV	% Δ	Initial	4KV	% Δ	
							Maximum	55.83	56.18	0.88	92.47	92.44	0.25
							Minimum	49.24	46.74	-12.47	91.52	91.43	-0.27
							Mean	52.13	51.46	-1.28	91.95	91.96	0.02
18	Solderability	J-STD-002C Method B1	4 hours @ 155°C dry heat @ 255°C. 90° dipping angle.	95% or greater coverage on "A" (seating plane) per J-STD-002C	15	NA	Inductance (μ H)			DC Resistance (m Ω)			
							Initial	4KV	% Δ	Initial	4KV	% Δ	
							Maximum	55.83	56.18	0.88	92.47	92.44	0.25
							Minimum	49.24	46.74	-12.47	91.52	91.43	-0.27
							Mean	52.13	51.46	-1.28	91.95	91.96	0.02
18	Solderability	J-STD-002C Method B1	4 hours @ 155°C dry heat @ 255°C. 90° dipping angle.	95% or greater coverage on "A" (seating plane) per J-STD-002C	15	NA	Std Dev	2.21	2.85	3.57	0.33	0.30	0.14
							Pass						



IHLP5050FDER560M5A TEST RESULTS

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas. Temp.													
19	Electrical Characterization	User Specification	Min, Max, Mean, and Standard Deviation @ Min (-55C), Room, and Max (+125C) operating temperatures. After mounted, allow +/-5% shift DCR at room temp. -55C/+125C DCR Max calculated using temp conversion for copper: $R_2 = [(T_2 + 234.5) / (234.5 + T_A)] * 1.05R_A$ (A = Ambient, 2 = new con)	Final Test: L= ±20% of initial, DCR per calculated limits described in test conditions. L test for -55C & +125C = ±20% initial	30			Inductance (μH)			DC Resistance (mΩ)								
								Initial			Initial								
						-55 deg. C	Maximum	54.166		64.840									
							Mimimum	45.169		62.960									
							Mean	50.288		63.605									
							Std Dev	1.968		0.372									
						+25 deg. C		Initial		Initial									
							Maximum	54.253		92.710									
							Mimimum	45.102		91.000									
							Mean	50.315		91.975									
						Std Dev	2.021		0.369										
						+155 deg. C		Initial		Initial									
							Maximum	54.717		129.440									
							Mimimum	45.523		126.440									
							Mean	50.733		127.986									
						Std Dev	2.060		0.697										
21	Board Flex	AEC-Q200-005 Appendix 2	2mm minimum flex for 60 (+5) sec	Pass all criteria as defined in DPS-11,865 VA1 L= ±20% of initial, DCR = ±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)								
								Initial	Final	%Δ	Initial	Final	%Δ						
						+25 deg. C	Maximum	57.059	56.960	1.554	93.330	93.390	1.031						
							Mimimum	47.918	48.259	-0.497	92.120	92.130	-1.106						
							Mean	51.137	51.425	0.565	92.730	92.787	0.062						
							Std Dev	2.305	2.299	0.390	0.347	0.343	0.311						
						22	Terminal Strength	AEC-Q200-006 Appendix 1	Force of 1.8kg (17.7 N) for 60 seconds	Pass all criteria as defined in DPS-11,865 VA1 L= ±20% of initial, DCR = ±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)		
														Initial	Final	%Δ	Initial	Final	%Δ
+25 deg. C	Maximum	55.859	55.863	0.584	93.330							93.470	0.465						
	Mimimum	48.458	48.464	-0.829	91.630							91.570	-0.325						
	Mean	52.285	52.282	-0.005	92.366							92.343	-0.026						
	Std Dev	2.017	2.018	0.198	0.388							0.494	0.190						



IHLP5050FDER100M5A TEST RESULTS

- This data represents parts manufactured in the BeerSheva, Israel manufacturing facility.



IHLP5050FDER100M5A

Test #	Description	Ref. Spec. Meth / Cond	Test Conditions	End Point Δ requirements	Sample Size	Meas Temp							
0	3X Reflow Preconditioning for lead-free products	ICP-10,373	As specified in sections 6.3 thru 6.4 in ICP-10,373										
1	Pre- and Post- Stress Electrical Test	IHLP Data Sheet	L (μ H) – 100KHz and 250mV DCR – 25°C Ambient	L=±15% of initial, DCR =±15% of initial	All tests requiring electrical data								
3	High Temp Exposure	IEC-60068 Part 2-2 test group BA	155C for 2000 hours, unpowered readings at 0, 250, 500, 1000 and 2000 hour intervals. Initial (0 hr.) and final (2000 hr.) readings at LT/RT/HT LT=Low Temperature=- 55°C, RT=Room Temperature=+25°C, HT= High Temperature=+125°C for -A1/1A models. HT=High Temperature =+155° C for -5A models.	L=±20% of initial, DCR =±20% of initial	77			Inductance (μ H)			DC Resistance ($m\Omega$)		
								Initial	Final	% Δ	Initial	Final	% Δ
						-55 deg. C	Maximum	9.496	10.101	9.308	10.996	10.984	16.071
							Minimum	8.172	8.912	6.055	9.178	10.476	-2.737
							Mean	8.784	9.463	7.741	10.781	10.708	-0.649
							Std Dev	0.231	0.211	0.638	0.198	0.097	2.125
						+25 deg. C		Initial	Final	% Δ	Initial	Final	% Δ
							Maximum	9.552	10.188	9.416	15.782	15.684	1.799
							Minimum	8.213	8.980	6.042	15.171	15.101	-1.897
							Mean	8.838	9.534	7.890	15.532	15.427	-0.674
							Std Dev	0.234	0.213	0.649	0.088	0.099	0.520
						+155 deg. C		Initial	Final	% Δ	Initial	Final	% Δ
							Maximum	9.553	10.430	11.889	23.570	23.170	0.703
							Minimum	8.214	9.170	8.674	22.290	22.240	-3.559
							Mean	8.834	9.747	10.350	23.123	22.799	-1.398
							Std Dev	0.232	0.222	0.688	0.220	0.202	0.806



IHLP5050FDER100M5A

								Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	9.409	9.413	0.230	10.992	11.109	3.120
Mimimum	8.086	8.082	-0.111	10.520	10.554		-1.805						
Mean	8.728	8.734	0.077	10.790	10.818		0.264						
Std Dev	0.247	0.247	0.080	0.095	0.097		1.011						
+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	9.478	9.471	0.129	15.654	15.868	1.975						
	Mimimum	8.125	8.115	-0.370	15.313	15.208	-1.215						
	Mean	8.784	8.781	-0.037	15.465	15.576	0.716						
	Std Dev	0.250	0.248	0.081	0.069	0.118	0.630						
+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	9.457	9.465	0.182	23.280	23.340	1.867						
	Mimimum	8.108	8.108	-0.042	22.370	22.370	-1.454						
	Mean	8.771	8.777	0.079	22.845	22.954	0.478						
	Std Dev	0.248	0.248	0.039	0.170	0.179	0.666						



IHLP5050FDER100M5A

									Inductance (μH)			DC Resistance (mΩ)		
									Initial	Final	%Δ	Initial	Final	%Δ
4	Temperature Cycling	IEC-60068, Part 2.14 test group Na	-55°C to +125°C (+155° C for -5A models) dwell time = 30 min. transfer time ≤10 sec. no. of cycles = 1000 unpowered initial (0 cycles) and final 1000 cycles). Readings at LT/RT/HT	L= ±20% of initial, DCR = ±20% of initial	77	-55 deg. C	Maximum		9.319	9.467	2.590	10.996	10.885	0.859
							Minimum		8.276	8.466	1.585	10.561	10.548	-2.901
							Mean		8.721	8.902	2.079	10.756	10.669	-0.806
							Std Dev		0.227	0.219	0.230	0.072	0.064	0.602
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ	
							Maximum		9.388	9.531	2.562	15.763	15.591	0.003
							Minimum		8.338	8.532	1.525	15.311	15.266	-1.675
							Mean		8.779	8.960	2.059	15.530	15.417	-0.728
						Std Dev		0.229	0.218	0.247	0.090	0.076	0.335	
						+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ	
							Maximum		9.347	9.699	4.581	23.520	23.380	3.373
							Minimum		8.339	8.676	3.557	21.940	22.620	-1.334
							Mean		8.758	9.109	4.011	22.967	23.014	0.215
						Std Dev		0.222	0.224	0.225	0.294	0.179	0.875	

									Inductance (μH)			DC Resistance (mΩ)		
									Initial	Final	%Δ	Initial	Final	%Δ
7	Biased Humidity	IEC-60068 Part 2-67	emperature = 85°C ±20°C Humidity = 85% ±5% RH Duration = 1000 hours Power = No Power Initial (0hr.) and final (1000hr.) readings at LT/RT/HT	L= ±20% of initial, DCR = ±20% of initial	77	-55 deg. C	Maximum		9.190	9.169	0.354	10.974	10.969	2.395
							Minimum		8.070	8.088	-0.406	10.496	10.565	-2.681
							Mean		8.727	8.723	-0.046	10.762	10.779	0.167
							Std Dev		0.233	0.229	0.151	0.098	0.077	0.986
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ	
							Maximum		9.241	9.207	0.245	15.760	15.722	3.083
							Minimum		8.129	8.140	-0.503	14.986	15.142	-2.180
							Mean		8.784	8.773	-0.125	15.411	15.494	0.552
						Std Dev		0.234	0.227	0.138	0.164	0.105	1.173	
						+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ	
							Maximum		9.237	9.241	0.666	23.310	23.410	3.244
							Minimum		8.154	8.208	-0.125	22.180	21.880	-3.697
							Mean		8.782	8.805	0.263	22.793	23.009	0.952
						Std Dev		0.230	0.222	0.146	0.199	0.218	1.051	



IHLP5050FDER100M5A

								Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
8	Operational Life	MIL-STD-202, Method 108A	Temperature = 85°C for -1A/A1 models. Temperature =115° C for 5A models. Duration = 2000hrs. Pow er = As noted on the test request. Readings a 0, 250, 500, 1000 and 2000 hour intervals. Initial (0 hr.) and final (2000 hr.) readings at LT/RT/HT	L=±20% of initial, DCR =±20% of initial	77	-55 deg. C	Maximum	9.423	9.607	2.745	10.994	11.045	1.880
							Mimimum	8.163	8.336	1.661	10.676	10.700	-1.690
							Mean	8.727	8.927	2.292	10.786	10.816	0.277
							Std Dev	0.242	0.243	0.245	0.068	0.072	0.714
						+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	9.512	9.733	3.359	15.969	15.857	1.460
							Mimimum	8.221	8.427	1.989	15.408	15.402	-0.939
							Mean	8.783	9.025	2.757	15.604	15.592	-0.072
						+155 deg. C	Std Dev	0.246	0.248	0.290	0.129	0.113	0.595
								Initial	Final	%Δ	Initial	Final	%Δ
							Maximum	9.502	9.749	4.206	23.470	23.560	1.626
							Mimimum	8.235	8.504	2.349	22.750	22.400	-1.582
							Mean	8.788	9.080	3.329	23.144	23.177	0.148
							Std Dev	0.240	0.251	0.404	0.176	0.179	0.629
9	External Visual	MIL-STD-883G Method 2009.9	Inspect construction and workmanship.	Pass all criteria as defined in DPS-11,865 VA1	All	na	Pass						
10	Physical Dimensions	JESD22 Method JB-100	Verify physical dimensions per part specification	All parts within dimensional tolerance per data sheet	30	na	Pass						
12	Resistance to Solvents	MIL-STD-202G Method 215K	Add Aqueous wash chemical. OKEM Clean or equivalent. Do not use banned solvents.	Pass all criteria as defined in DPS-11,865 VA1 L=±20% of initial, DCR =±20% of initial	5	na	Pass						



IHLP5050FDER100M5A

13	Mechanical Shock	IEC-60068 part 2.27 test group Ea with precondition per 0 above	Pulse Shape-Half Sine Normal Pulse Length 6ms Peak acceleration-100g No. shocks-6 each in both directions of each axis (total of 36) Initial and final readings at LT/RT/HT	L=±20% of initial, DCR =±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	9.314	9.320	0.221	10.929	10.980	0.851
Mimimum	8.361	8.364	-0.093	10.640	10.638		-0.215						
Mean	8.801	8.809	0.088	10.744	10.777		0.312						
Std Dev	0.232	0.230	0.077	0.077	0.091		0.264						
+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	9.383	9.379	0.166	15.629	15.626	0.330						
	Mimimum	8.422	8.421	-0.100	15.369	15.278	-1.123						
	Mean	8.859	8.862	0.041	15.473	15.452	-0.132						
+155 deg. C	Std Dev	0.236	0.232	0.069	0.061	0.073	0.378						
		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	9.340	9.352	0.203	23.250	23.210	3.135						
	Mimimum	8.409	8.420	-0.041	22.290	22.530	-0.879						
	Mean	8.843	8.853	0.116	22.791	22.921	0.576						
	Std Dev	0.229	0.230	0.039	0.253	0.167	0.878						

14	Vibration	IEC-60068 PART 2-6 TEST GROUP Fc. With precondition per 0 above	Pulse Shape-sine wave range of frequency 1 10-55Hz. Amplitude ±0.75mm Range of frequency 2 55-2000Hz Amplitude; 10G Frequency Sw eep: 1 oct./min. Duration: 24 h each of 3 axis. Initial and final readings at LT/RT/HT	L=±20% of initial, DCR =±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	9.427	9.423	0.264	11.047	10.808	0.288
Mimimum	8.293	8.309	-0.195	10.663	10.626		-2.462						
Mean	8.708	8.718	0.116	10.786	10.724		-0.571						
Std Dev	0.248	0.244	0.099	0.079	0.050		0.778						
+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	9.482	9.472	0.244	15.694	15.608	0.367						
	Mimimum	8.349	8.363	-0.105	15.383	15.239	-1.706						
	Mean	8.763	8.771	0.095	15.495	15.422	-0.475						
+155 deg. C	Std Dev	0.249	0.244	0.084	0.066	0.089	0.546						
		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	9.454	9.448	0.326	23.240	23.040	-0.087						
	Mimimum	8.342	8.353	-0.065	22.670	22.280	-3.966						
	Mean	8.754	8.765	0.132	23.055	22.743	-1.352						
	Std Dev	0.244	0.241	0.079	0.127	0.209	0.883						



IHLP5050FDER100M5A

								Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						-55 deg. C	Maximum	9.025	9.023	0.285	11.086	10.961	-0.456
Mimimum	8.438	8.462	-0.024	10.739	10.663		-1.128						
Mean	8.703	8.717	0.157	10.858	10.776		-0.753						
Std Dev	0.165	0.161	0.077	0.100	0.085		0.179						
+25 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	9.087	9.082	0.214	15.642	15.633	0.000						
	Mimimum	8.502	8.520	-0.067	15.410	15.392	-0.408						
	Mean	8.762	8.767	0.048	15.514	15.502	-0.075						
	Std Dev	0.167	0.163	0.074	0.063	0.067	0.077						
+155 deg. C		Initial	Final	%Δ	Initial	Final	%Δ						
	Maximum	9.067	9.077	0.217	23.280	23.210	0.087						
	Mimimum	8.507	8.521	-0.041	22.870	22.760	-0.558						
	Mean	8.753	8.764	0.126	23.074	23.032	-0.181						
	Std Dev	0.165	0.164	0.051	0.103	0.111	0.176						



IHLP5050FDER100M5A

15	Resistance to Solder Heat	MIL-STD-202G Method 210F Condition K	IR/convection reflow. 250 ± 5°C for 30 ± 5sec. Ramp rate 1°C/s to 4°C/; Above 183°C for 90s-120s	L= ±20% of initial, DCR = ±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						+25 deg. C	Maximum	9.122	9.135	1.619	15.872	15.817	-0.044
							Minimum	8.250	8.350	-0.348	15.584	15.556	-0.595
							Mean	8.722	8.775	0.624	15.731	15.692	-0.251
							Std Dev	0.250	0.223	0.552	0.062	0.060	0.103
17	ESD	AEC-Q200-002	Determine the Classification of the part.	L= ±20% of initial, DCR = ±20% of initial	15			Inductance (μH)			DC Resistance (mΩ)		
								Initial	25KV	%Δ	Initial	25KV	%Δ
						+25 deg. C	Maximum	9.196	9.229	1.096	15.811	15.826	0.595
							Minimum	8.438	8.513	0.003	15.576	15.601	-0.753
							Mean	8.934	8.987	0.601	15.678	15.693	0.096
							Std Dev	0.176	0.170	0.245	0.076	0.065	0.334
18	Solderability	J-STD-002C Method B1	4 hours @ 155°C dry heat @ 255°C. 90° dipping angle.	95% or greater coverage on "A" (seating plane) per J-STD-002C	15	NA	Pass						



IHLP5050FDER100M5A

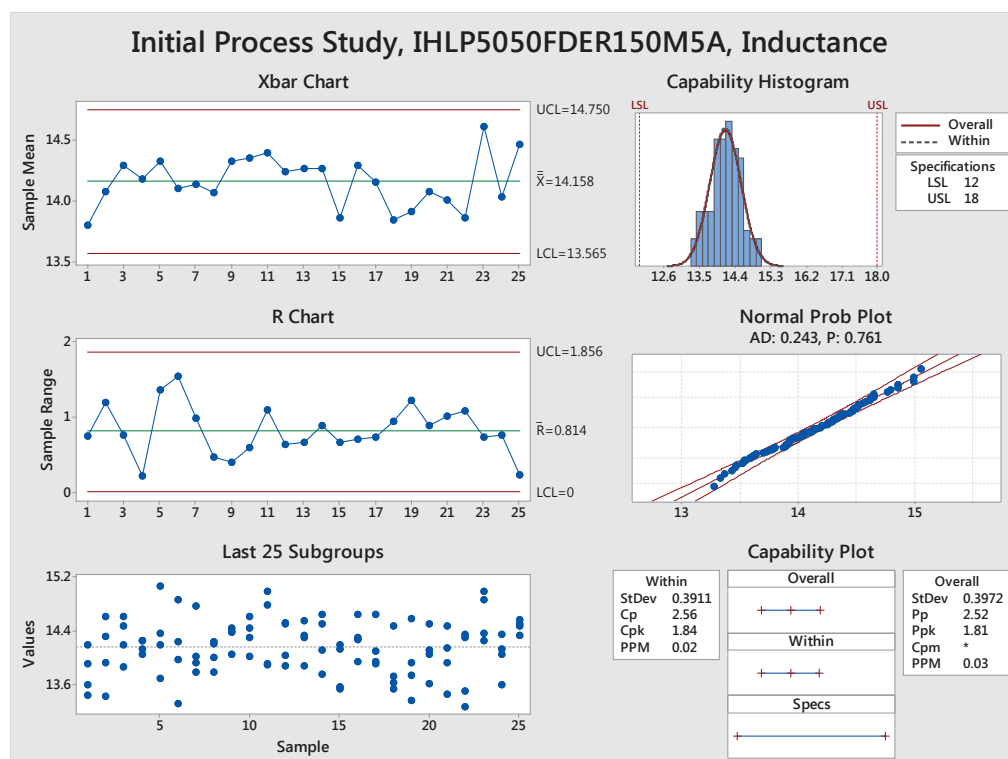
19	Electrical Characterization	User Specification	Min, Max, Mean, and Standard Deviation @ Min (-55C), Room, and Max (+125C) operating temperatures. After mounted, allow +/-5% shift DCR at room temp. -55C/+125C DCR Max calculated using temp conversion for copper: $R_2 = [(T_2 + 234.5) / (234.5 + T_A)] * 1.05R_A$ (A = Ambient, 2 = new con)	Final Test: L=±20% of initial, DCR per calculated limits described in test conditions. L test for -55C & +125C = ±20% initial	30			Inductance (μH)			DC Resistance (mΩ)		
								May			Initial		
						-55 deg. C	Maximum	9.427			11.047		
							Minimum	8.293			10.663		
							Mean	8.708			10.786		
							Std Dev	0.248			0.079		
						+25 deg. C		Initial			Initial		
							Maximum	9.482			15.694		
							Minimum	8.349			15.383		
							Mean	8.763			15.495		
							Std Dev	0.249			0.066		
						+155 deg. C		Initial			Initial		
							Maximum	9.454			23.240		
							Minimum	8.342			22.670		
							Mean	8.754			23.055		
							Std Dev	0.244			0.127		
21	Board Flex	AEC-Q200-005 Appendix 2	2mm minimum flex for 60 (+5) sec	Pass all criteria as defined in DPS-11,865 VA1 L=±20% of initial, DCR =±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						+25 deg. C	Maximum	9.516	9.558	0.444	15.784	15.818	0.249
							Minimum	8.355	8.374	0.169	15.600	15.635	-0.025
							Mean	8.824	8.851	0.312	15.711	15.730	0.123
							Std Dev	0.299	0.301	0.057	0.052	0.048	0.084
22	Terminal Strength	AEC-Q200-006 Appendix 1	Force of 1.8kg (17.7 N) for 60 seconds	Pass all criteria as defined in DPS-11,865 VA1 L=±20% of initial, DCR =±20% of initial	30			Inductance (μH)			DC Resistance (mΩ)		
								Initial	Final	%Δ	Initial	Final	%Δ
						+25 deg. C	Maximum	9.480	9.475	0.294	15.834	15.885	0.414
							Minimum	8.342	8.355	-0.240	15.540	15.535	-0.184
							Mean	8.919	8.938	0.114	15.674	15.698	0.182
							Std Dev	0.272	0.270	0.138	0.077	0.078	0.137

Production Part Approval Process

The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements

Initial Process Study IHLP5050FDER150M5A, Inductance

Inductance (uH)					
1	14.2	26	14.77	51	13.89
2	13.91	27	13.8	52	14.3
3	13.46	28	13.93	53	13.77
4	13.61	29	14.21	54	14.51
5	14.32	30	14.25	55	14.65
6	14.61	31	13.79	56	14.12
7	13.93	32	14.01	57	13.54
8	13.43	33	14.06	58	14.13
9	14.2	34	14.38	59	13.58
10	14.62	35	14.45	60	14.19
11	13.87	36	14.4	61	14.3
12	14.47	37	14.03	62	13.95
13	14.26	38	14.44	63	14.28
14	14.13	39	14.31	64	14.65
15	14.26	40	14.62	65	14.1
16	14.05	41	14.99	66	14.65
17	15.06	42	13.9	67	13.95
18	13.7	43	13.92	68	13.92
19	14.19	44	14.79	69	13.54
20	14.37	45	14.52	70	14.47
21	14.86	46	14.04	71	13.64
22	13.98	47	14.5	72	13.73
23	13.33	48	13.89	73	13.37
24	14.24	49	14.33	74	13.75
25	14.03	50	14.55	75	13.94

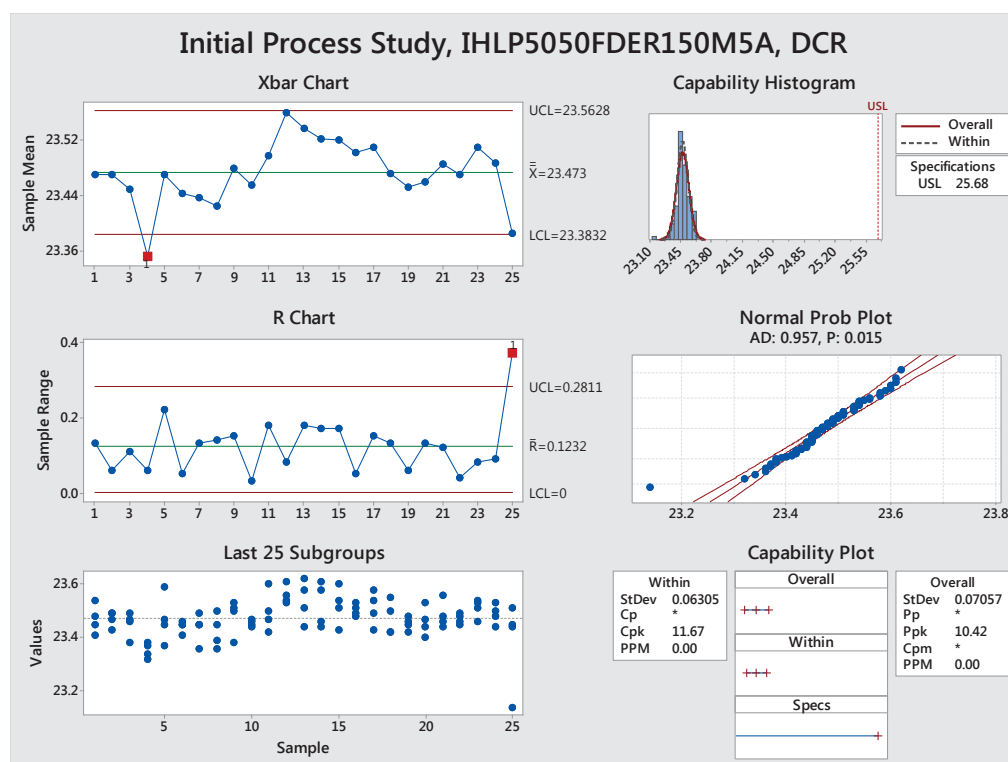


Production Part Approval Process

The following PPAP documentation is assembled according to AIAG, 4th Edition PPAP Manual and applicable customer requirements

Initial Process Study IHLP5050FDER150M5A, DC Resistance

DCR (mOhm)							
1	23.54	26	23.45	51	23.51	76	23.48
2	23.48	27	23.45	52	23.44	77	23.47
3	23.45	28	23.36	53	23.44	78	23.4
4	23.41	29	23.5	54	23.61	79	23.53
5	23.49	30	23.45	55	23.46	80	23.44
6	23.47	31	23.39	56	23.58	81	23.48
7	23.49	32	23.36	57	23.43	82	23.46
8	23.43	33	23.51	58	23.6	83	23.56
9	23.49	34	23.38	59	23.51	84	23.44
10	23.46	35	23.53	60	23.54	85	23.49
11	23.47	36	23.5	61	23.49	86	23.45
12	23.38	37	23.47	62	23.53	87	23.48
13	23.38	38	23.46	63	23.51	88	23.46
14	23.37	39	23.44	64	23.48	89	23.51
15	23.34	40	23.45	65	23.43	90	23.46
16	23.32	41	23.42	66	23.54	91	23.54
17	23.59	42	23.5	67	23.49	92	23.53
18	23.47	43	23.47	68	23.58	93	23.53
19	23.45	44	23.6	69	23.42	94	23.44
20	23.37	45	23.54	70	23.55	95	23.5
21	23.45	46	23.56	71	23.42	96	23.48
22	23.45	47	23.53	72	23.5	97	23.51
23	23.46	48	23.61	73	23.46	98	23.14
24	23.41	49	23.58	74	23.45	99	23.45
25	23.49	50	23.62	75	23.42	100	23.44

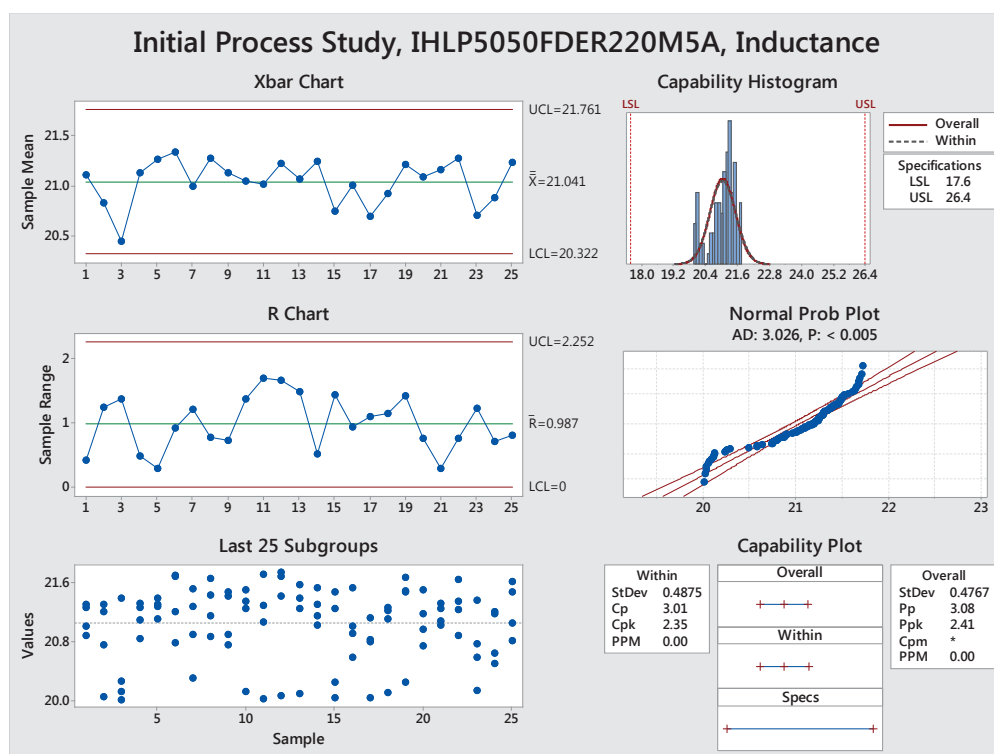


Production Part Approval Process

The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements

Initial Process Study IHL5050FDER220M5A, Inductance

Inductance (uH)					
1	21.2993	26	20.8877	51	21.5691
2	21.0088	27	21.2753	52	21.2484
3	20.8839	28	21.5063	53	21.0146
4	21.2631	29	21.6493	54	21.3035
5	21.2953	30	21.1476	55	21.1449
6	20.054	31	20.871	56	21.5271
7	20.7485	32	21.4309	57	21.4614
8	21.2014	33	20.7492	58	20.0304
9	20.0126	34	20.8974	59	20.2415
10	20.1174	35	21.4734	60	21.2463
11	20.2585	36	21.4163	61	20.9104
12	21.3873	37	21.2416	62	20.5877
13	21.3146	38	20.1251	63	21.5244
14	20.8408	39	21.4899	64	21.0005
15	21.0949	40	21.3396	65	20.8008
16	21.2552	41	20.0194	66	20.0319
17	21.38	42	21.2837	67	20.8196
18	21.2985	43	21.7132	68	21.1187
19	21.2706	44	21.0645	69	21.2596
20	21.1028	45	21.6791	70	21.2113
21	21.1945	46	21.4134	71	20.1113
22	21.6954	47	20.0677	72	21.0978
23	21.6772	48	21.7301	73	21.6584
24	20.7833	49	21.3804	74	21.4719
25	20.2962	50	20.0862	75	20.2449

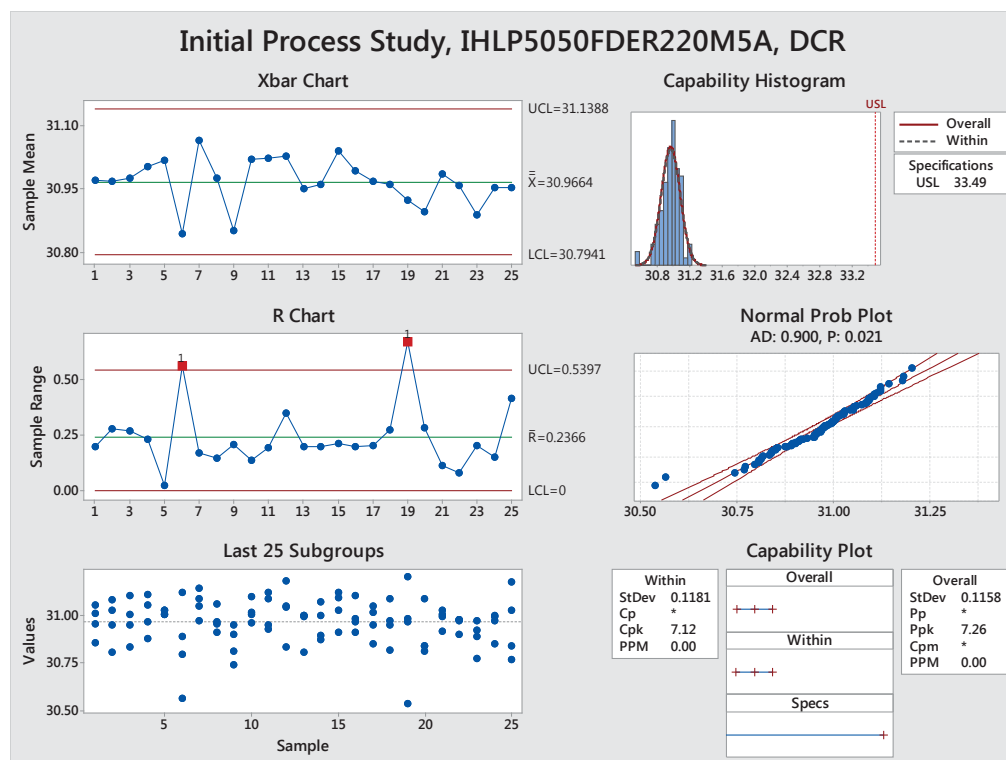


Production Part Approval Process

The following PPAP documentation is assembled according to AIAG, 4th Edition PPAP Manual and applicable customer requirements

Initial Process Study IHL5050FDER220M5A, DC Resistance

DCR (mOhm)							
1	31.055	26	31.145	51	30.808	76	30.537
2	30.857	27	31.052	52	30.996	77	30.839
3	30.955	28	30.975	53	31.073	78	31.091
4	31.01	29	30.956	54	30.893	79	30.812
5	31.082	30	30.914	55	30.875	80	30.84
6	30.951	31	31.06	56	31	81	30.993
7	31.029	32	30.968	57	30.914	82	31.005
8	30.807	33	30.949	58	31.026	83	31.027
9	30.837	34	30.901	59	31.093	84	30.915
10	31.106	35	30.743	60	31.122	85	30.979
11	30.95	36	30.814	61	31.106	86	30.973
12	31.007	37	31.097	62	30.986	87	30.901
13	30.881	38	31.007	63	30.966	88	30.978
14	31.111	39	30.96	64	30.91	89	30.921
15	30.968	40	31.019	65	30.952	90	30.771
16	31.054	41	30.931	66	31.052	91	30.891
17	31.006	42	31.088	67	31.014	92	30.97
18	31.028	43	30.95	68	30.85	93	30.998
19	31.005	44	31.123	69	31.091	94	30.85
20	31.027	45	31.182	70	30.975	95	30.971
21	30.564	46	30.835	71	30.953	96	30.994
22	30.796	47	31.043	72	30.819	97	31.025
23	30.891	48	31.052	73	31.203	98	31.179
24	31.122	49	31.002	74	30.983	99	30.841
25	31.086	50	30.998	75	30.966	100	30.768



Production Part Approval Process

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AIAG, 4th Edition PPAP Manual and applicable customer requirements**

Use the control buttons below to navigate through the PPAP sections.

Section 12: Qualified Laboratories

Vishay / Dale Electronics

1505 East Hwy 50 Yankton, SD 57078, USA Phone (605) 665-9301 Fax (605) 668-4247

ONE OF THE WORLD'S LARGEST MANUFACTURERS OF DISCRETE SEMICONDUCTORS AND PASSIVE COMPONENTS

Production Part Approval Process

The following PPAP documentation is assembled according to AIAG, 4th Edition PPAP Manual and applicable customer requirements

Use the control buttons below to navigate through the PPAP sections.

Section 13: Appearance Approval Report

Inductors, like many other electronic components are specified for their electrical properties. There are no specific requirements stated for the physical appearance of inductors, e.g. color of inductors. Therefore, the Appearance Approval Report does not apply in this case.

Vishay / Dale Electronics

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Production Part Approval Process

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Use the control buttons below to navigate through the PPAP sections.

Section 14: Sample Product

Sample product from the Vishay Manufacturing Facility is available upon request

Production Part Approval Process

**The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements**

Use the control buttons below to navigate through the PPAP sections.

Section 15: Master Sample

Master Sample(s) will be retained at the Vishay Manufacturing Facility with a copy of the PPAP

Production Part Approval Process

**The following PPAP documentation is assembled according to
AIAG, 4th Edition PPAP Manual and applicable customer requirements**

Use the control buttons below to navigate through the PPAP sections.

[Section 16: Checking Aids](#)

Checking Aids are not required for this electronic component

Vishay / Dale Electronics

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Production Part Approval Process

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Use the control buttons below to navigate through the PPAP sections.

Section 17: Records of Compliance

Moisture Sensitivity Level: 1

Production Part Approval Process

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AIAG, 4th Edition PPAP Manual and applicable customer requirements**

Use the control buttons below to navigate through the PPAP sections.

[Section 19: Bulk Material Requirements](#)

Bulk Material Requirements do not apply to this Electronic Component.



IHLP Standards of Manufacture

IHLP INTRODUCTION SURFACE IRREGULARITIES CRITERIA FOR REJECTION SUMMARY

INTRODUCTION

Scope

This document was written for the purpose of helping customers better understand the product they are purchasing. It will give the customer an idea as to the type of cosmetic irregularities that may occur from time to time during the manufacture of the component itself or during customer use of the component.

This document also discusses the criteria that have been developed for rejection of irregularities that are determined to be excessive.

While it would be desirable to have cosmetically perfect IHLP inductors, the powdered iron manufacturing technique has cosmetic limitations.

Certified test labs have performed extensive environmental testing on IHLP's with and without cosmetic imperfections according to AEC-Q200 standards for such tests as thermal shock, mechanical shock, vibration, humidity and others. This testing has shown that the cosmetic imperfections listed in this document do not affect the performance or reliability of the IHLP inductor. Test results are available upon request.

Product

The IHLP inductor is unique from most inductors. The inductor body is a soft magnetic composite (SMC), not a ferrite. It is made from an iron powder mixture and cemented together using a resin binder. This powder mixture, when pressed around the inductor coil, greatly enhances the electrical properties of the inductor and gives protection from environmental forces. After pressing, the component is cured in an oven to increase the bonding strength of the resin binders with the iron powder, yielding excellent electrical and physical properties.

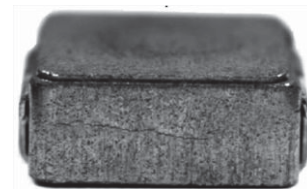
The IHLP inductor provides the best combination of:

- Inductance
- Low Core Loss
- Saturation
- Temperature Stability
- Smallest Footprint
- Lowest Profile

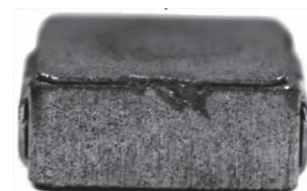
Surface irregularities

The following pages include descriptions of the most common irregularities seen on IHLP inductors. Common causes are described along with variations in their magnitude. Customers may at some time see one or all of these irregularities.

Those that are determined to adversely affect the customer's use of the component are rejected, but minor (acceptable) irregularities will occasionally be present. With the use of this guide, a customer will better understand the effect of each irregularity.



Cracks



Chips



Oxidation

IHLP Standards of Manufacture

CRACKS

Cracks within the inductor body are unavoidable during the manufacturing process. Small cracks are caused by die wall friction when the parts are ejected during the pressing process and by expansion of the coil during the process of curing the resin binder in the powdered iron body. Unlike ferrite material, cracks on the IHLP body do not affect the electrical performance of the component.

Reliability testing has shown that even cracks in excess of 0.005" will not cause the component to fail electrically or physically in field application. Acceptance widths are adopted based on the ability to detect cracks both at the component and circuit level.



Terminal area crack, acceptable

Cracks coming from the top corner of the terminal are a normal occurrence and are caused by terminal expansion during curing operations.



Negligible crack, acceptable

Negligible cracks are those that are nearly invisible without magnification.



Minor crack, acceptable

Minor cracks are those that are visible without magnification but are not apparent without close inspection.



Moderate crack, rejectable

Moderate cracks are those that are obvious upon examination and continue across most of the component.



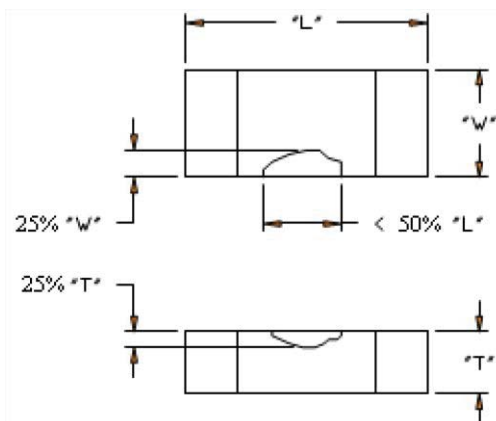
Major crack, rejectable

Major cracks are those that are obvious to a customer and would possibly result in large chip-outs that would expose the coil and lead frame.

IHLP Standards of Manufacture

CHIPS

Chipping of the inductor body can occur during normal processing and testing of the inductor. The acceptance criteria for chipping vary with the size of the component, but current acceptance standards are based on IPCA-610. The effect of chipping is negligible as long as the inductor coil is not showing. See IPC standard for class 1 and 2 components below.



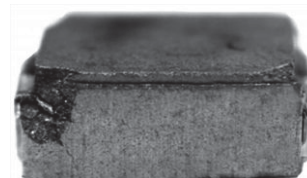
T	25 % of the thickness
W	25 % of the width
L	50 % of the length

Chips typically occur on the edges and corners of the inductor body. They are slightly darker in color and rougher in appearance than the surrounding material.



Minor chipping, acceptable

Minor chips in the inductor body are those that are typically shallow imperfections that occur on the corners and edge of components. No coil wire or lead frame is showing and the chip does not affect the performance or reliability of the component.



Major chipping, rejectable

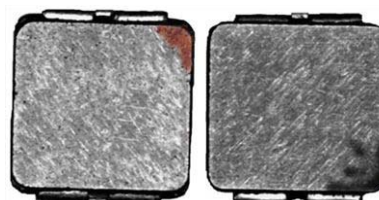
Major chips in the inductor body are those that are very obvious to the customer and may expose the wire coil or lead frame.

OXIDATION

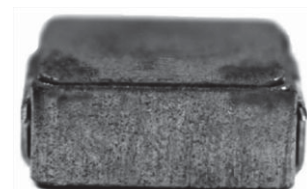
The IHLP inductor is predominately iron and oxidation may occur in a small percentage of the inductors. Resin binders give moderate protection, but some slight oxidation may occur. All components should be stored away from heat, humidity and ionized atmospheres as much as possible before mounting.

Basic steps should be taken in order to limit surface oxidation, including keeping the IHLP inductors sealed in their packaging until PCB mounting.

In the case that oxidation does occur, the effects are contained to the surface of the component and do not penetrate into the core material. No electrical effects have ever been documented due to oxidation of the IHLP product. Oxidation should never be considered a reliability risk.



Top view



Side view

IHLP Standards of Manufacture

OTHER

A very small number of other irregularities have been reported. These occur at an exceedingly low rate and typically do not affect the components electrically. These include:

Foreign material may be seen pressed into the upper terminals. This material is of the same material as the inductor body and should not be a reason for rejection unless solderability is affected.



Foreign material: Acceptable

Scratches may be seen on the surface of the inductor body. Scratches are an acceptable surface irregularity.



Scratch: Acceptable

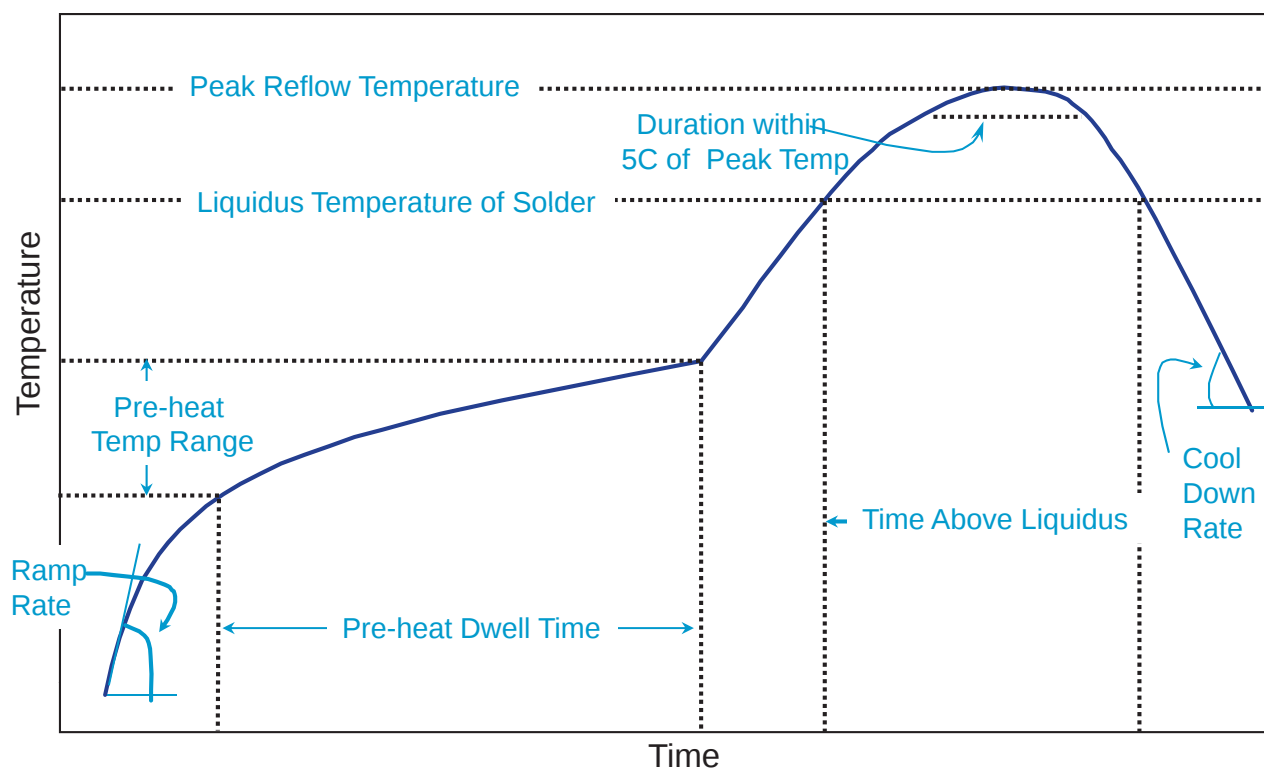
SUMMARY

The IHLP inductor is comprised of an iron powder body compressed around a coil. Due to the fact that this iron powder body is not solid like ferrite material, irregularities such as cracks and chips do not affect the electrical properties, or the reliability of the component. Criteria have been determined for the acceptability of the components that allow for a robust manufacturing process as well as an acceptable degree of cosmetic irregularity.

Reliability testing has been done on the effects of cracking of the iron powder body and on the oxidation of the iron particles that are present on the surface. Testing has shown no reliability issues from either of these cosmetic differences.



Typical Reflow Soldering Profile





Lead Free Solder (SnAgCu) Reflow Profile Attributes

•Profile Attribute	•Value
•Peak Reflow Temperature	•255(+/-5)C
•Time within 5C of Peak Temperature	•20 seconds max
•Liquidus Temperature of Solder	•~217C
•Cool Down Rate	•3.5C/sec max
•Time Above Liquidus	•30 to 90 seconds
•Pre-heat Temperature Range	•145 to 170C
•Pre-heat Dwell Time	•20-1200s
•Maximum Ramp Rate	•2C/sec max